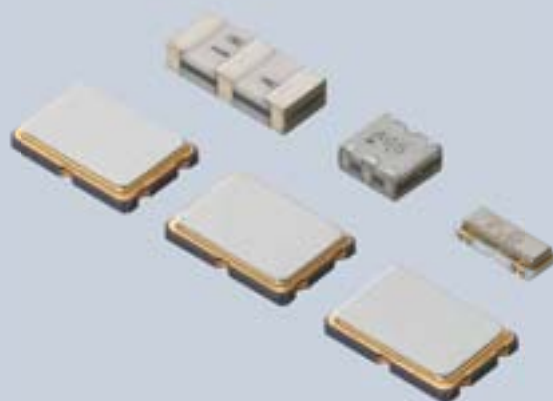


Ceramic Filters (CERAFIL)/ Crystal Filters





EU RoHS Compliant

- All the products in this catalog comply with EU RoHS.
- EU RoHS is "the European Directive 2011/65/EU on the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment."
- For more details, please refer to our web page, "Murata's Approach for EU RoHS" (<https://www.murata.com/en-eu/support/compliance/rohs>).

Contents

Product specifications are as of October 2019.

| | |
|-----------------------|----|
| Selection Guide | p2 |
| Part Numbering | p3 |

| | |
|---|-----|
| 1 Ceramic Filters (CERAFIL) Chip Type SFECF Series | |
| Features/Appearance/Dimensions | p6 |
| Part Number List | p6 |
| Standard Center Frequency Rank Code | p7 |
| Standard Land Pattern Dimensions | p7 |
| Test Circuit | p7 |
| Frequency Characteristics | p8 |
| Spurious | p10 |
| Notice | p12 |
| Packaging | p14 |

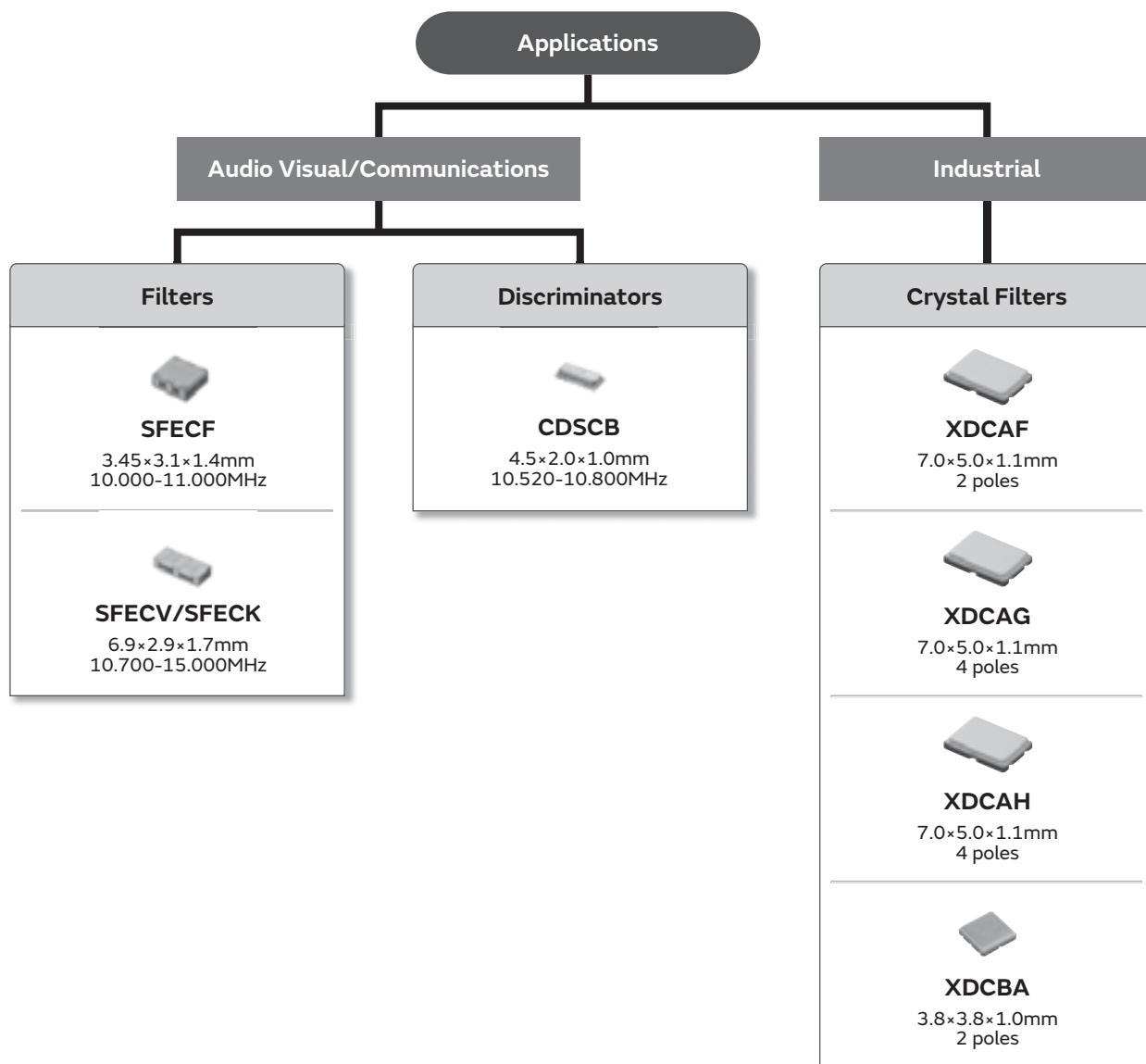
| | |
|---|-----|
| 2 Ceramic Filters (CERAFIL) Chip Type SFECV/SFECK Series | |
| Features/Applications/Appearance/Dimensions | p15 |
| Part Number List | p15 |
| Standard Center Frequency Rank Code | p16 |
| Standard Land Pattern Dimensions | p16 |
| Test Circuit | p16 |
| Frequency Characteristics | p16 |
| Spurious | p17 |
| Notice | p18 |
| Packaging | p20 |

| | |
|---|-----|
| 3 Ceramic Discriminator (CERAFIL) Chip Type CDSCB Series | |
| Features/Appearance/Dimensions | p21 |
| Part Number List | p21 |
| Standard Center Frequency Rank Code | p21 |
| Standard Land Pattern Dimensions | p22 |
| Test Circuit | p22 |
| Recovered Audio Curve | p24 |
| S Curve | p25 |
| Notice | p26 |
| Packaging | p28 |

| | |
|---|-----|
| 4 Crystal Filters Chip Type XDCAF/XDCAG/XDCAH/XDCBA Series | |
| Features/Applications/Appearance/Dimensions | p29 |
| Series | p29 |
| Part Number List | p30 |
| Test Circuit | p31 |
| Frequency Characteristics | p32 |
| Spurious | p33 |
| Notice | p34 |
| Packaging | p36 |

Please check the MURATA website (<https://www.murata.com/>) if you cannot find a part number in this catalog.

Selection Guides



● Part Numbering

CERAFIL for FM

(Part Number)

| | | | | | | | |
|----|---|----|------|---|---|----|-----|
| SF | E | CF | 10M7 | F | A | A0 | -R0 |
| ① | ② | ③ | ④ | ⑤ | ⑥ | ⑦ | ⑧ |

① Product ID

| Product ID | |
|------------|-----------------|
| SF | Ceramic Filters |

② Oscillation/Number of Elements

| Code | Oscillation/Number of Elements |
|------|--|
| E | 2 Elements Thickness Expander Mode |
| T | 3 Elements Thickness Expander Mode |
| V | 2 Elements Thickness Expander Mode (2nd Harmonic) |
| K | 2 Elements Thickness Expander Mode (3rd Overtone) |

③ Structure/Size

| Code | Structure/Size |
|------|----------------|
| C□ | Chip Type |

□ is "A" or subsequent code, which indicates the structure/size.

④ Nominal Center Frequency

Expressed by four-digit alphanumerics. The unit is in hertz (Hz).
Decimal point is expressed by capital letter "M" in case of MHz.

⑤ 3dB Bandwidth

| Code | 3dB Bandwidth |
|------|---------------|
| C | 450kHz min |
| D | 350kHz min |
| E | 330kHz |
| F | 280kHz |
| G | 230kHz |
| H | 180kHz |
| J | 150kHz |
| K | 110kHz |
| L | 80kHz |
| M | 50kHz |
| N | 35kHz |

⑥ Center Frequency/Tolerance

| Code | Center Frequency | Tolerance |
|------|---|-----------|
| A | Center Frequency Mentioned by Specification | ±30kHz |
| F | Nominal Center Frequency | — |

3dB bandwidth of "F" signifies the frequency difference (both + and -) from reference frequency, which is nominal center frequency.

⑦ Series

| Code | Series |
|------|--|
| A0 | Two-digit Alphanumerics Express Series |

⑧ Packaging

| Code | Packaging |
|------|------------------------|
| -B0 | Bulk |
| -R0 | Embossed Taping ø180mm |
| -R1 | Embossed Taping ø330mm |

Radial taping is applied to lead type and embossed taping to chip type.
With non-standard products, two-digit alphanumerics indicating "Individual Specification" are added between "⑦Series" and "⑧Packaging."

CERAFIL

(Part Number)

| | | | | | | |
|----|---|----|------|----|----|-----|
| SF | S | KA | 4M50 | CF | 00 | -R1 |
| ① | ② | ③ | ④ | ⑤ | ⑥ | ⑦ |

① Product ID

| Product ID | |
|------------|-----------------|
| SF | Ceramic Filters |

② Oscillation/Numbers of Element

| Code | Oscillation/Numbers of Element |
|------|---------------------------------|
| S | 2 Elements Thickness Shear Mode |

③ Structure/Size

| Code | Structure/Size |
|------|----------------|
| K□ | Chip Type |

□ is "A" or subsequent code, which indicates the structure/size.

④ Nominal Center Frequency

Expressed by four-digit alphanumerics. The unit is in hertz (Hz).
Decimal point is expressed by capital letter "M" in case of MHz.

Discriminators for FM

(Part Number)

| | | | | | | | |
|----|---|----|------|---|---|-----|-----|
| CD | S | CB | 10M7 | G | A | 001 | -R0 |
| ① | ② | ③ | ④ | ⑤ | ⑥ | ⑦ | ⑧ |

① Product ID

| Product ID | |
|------------|----------------|
| CD | Discriminators |

② Oscillation

| Code | Oscillation |
|------|----------------------|
| S | Thickness Shear Mode |

③ Structure/Size

| Code | Structure/Size |
|------|----------------|
| C□ | Chip Type |

□ is "A" or subsequent code, which indicates the structure/size.

④ Nominal Center Frequency

Expressed by four-digit alphanumerics. The unit is in hertz (Hz).
Decimal point is expressed by capital letter "M" in case of MHz.

⑤ Series

| Code | Series |
|------|--|
| G | Two-digit Alphanumerics Express Series |

⑤ Product Specification Code (1)

| Code | Product Specification Code (1) |
|------|--------------------------------|
| BF | Tight Bandwidth Type |
| CF | Standard Bandwidth Type |
| DF | Broad Bandwidth Type |
| EF | Ultra-broad Bandwidth Type |

⑥ Product Specification Code (2)

| Code | Product Specification Code (2) |
|------|--------------------------------|
| 00 | Standard Type |

⑦ Packaging

| Code | Packaging |
|------|-------------------------|
| -B0 | Bulk |
| -R1 | Embossed Taping ø=330mm |

With non-standard products, two-digit alphanumerics indicating "Individual Specification" is added between "⑥ Product Specification Code (2)" and "⑦ Packaging."

⑥ Center Frequency/Tolerance

| Code | Center Frequency | Tolerance |
|------|---|-----------|
| A | Center Frequency Mentioned by Specification | ±30kHz |
| F | Nominal Center Frequency | — |

3dB bandwidth of "F" signifies the frequency difference (both + and -) from reference frequency, which is nominal center frequency.

⑦ IC

| Code | IC |
|------|----------------------------|
| 001 | Applicable IC Control Code |

⑧ Packaging

| Code | Packaging |
|------|-------------------------|
| -B0 | Bulk |
| -R0 | Embossed Taping ø=180mm |
| -R1 | Embossed Taping ø=330mm |

Radial taping is applied to lead type and embossed taping to chip type.
With non-standard products, an alphanumerics indicating "Individual Specification" is added between "⑦ IC" and "⑧ Packaging."

Crystal Filter

(Part Number)

| | | | | | | | | |
|-----------|----------|----------|----------|---------------|----------|----------|------------|-----------|
| XD | C | A | F | 21M400 | R | A | A00 | P0 |
| ① | ② | ③ | ④ | ⑤ | ⑥ | ⑦ | ⑧ | ⑨ |

① Product ID

| Product ID | |
|------------|----------------|
| XD | Crystal Filter |

② Type · Lead Style

| Code | Type · Lead Style |
|----------|-------------------|
| C | Monolithic SMD |

③ Size

| Code | Size |
|----------|------|
| A | 7050 |
| B | 3838 |

④ Structure

Expressed by one alphabetic character.

⑤ Nominal Center Frequency

Expressed by six-digit alphanumeric. The unit is in hertz (Hz).
Decimal point is expressed by capital letter "M".

⑥ Bandwidth

| Code | Bandwidth (3dB) |
|----------|---------------------|
| M | 6.800 to 8.199kHz |
| P | 10.000 to 11.999kHz |
| Q | 12.000 to 14.999kHz |
| R | 15.000 to 17.999kHz |

⑦ Number of Poles

| Code | Number of Poles |
|----------|-----------------|
| A | 2 (1 Element) |
| G | 4 (1 Element) |
| H | 4 (2 Elements) |

⑧ Individual Specification

| Code | |
|------------|---|
| *** | Three-digit Alphanumerics Express Individual Specification. |

⑨ Packaging (Packaging quantity is expressed by one-digit number in "**")

| Code | Packaging |
|--------------|-----------------------|
| P*/L* | Plastic Taping ø330mm |

High-reliability Type

| Part Number | Center Frequency (fo) (MHz) | Nominal Center Frequency (fn) (MHz) | 3dB Bandwidth (kHz) | Attenuation (kHz) | Insertion Loss (dB) | Ripple (dB) | Spurious Attenuation (1) (dB) | Spurious Attenuation (2) (dB) | Input/Output Impedance (ohm) |
|--------------------|-----------------------------|-------------------------------------|---------------------|-------------------|---------------------|-------------|--------------------------------|---------------------------------|------------------------------|
| SFECF10M7HA00S0-R0 | 10.700 ±30kHz | - | 180 ±40kHz | 470 max. | 4.0±2.0dB | 1.0 max. | 30 min. [within 9MHz to fo] | 30 min. [within fo to 12MHz] | 330 |
| SFECF10M7HF00S0-R0 | - | 10.700 | fn±25 min. | 510 max. | 8.0max. [at fn] | 1.0 max. | 30 min. [within 9MHz to fn] | 25 min. [within fn to 12MHz] | 330 |
| SFECF10M7GA00S0-R0 | 10.700 ±30kHz | - | 230 ±50kHz | 510 max. | 3.5±2.0dB | 1.0 max. | 30 min. [within 9MHz to fo] | 30 min. [within fo to 12MHz] | 330 |
| SFECF10M7GF00S0-R0 | - | 10.700 | fn±45 min. | 560 max. | 8.0max. [at fn] | 1.0 max. | 30 min. [within 9MHz to fn] | 25 min. [within fn to 12MHz] | 330 |
| SFECF10M7FA00S0-R0 | 10.700 ±30kHz | - | 280 ±50kHz | 590 max. | 3.0±2.0dB | 1.0 max. | 30 min. [within 9MHz to fo] | 30 min. [within fo to 12MHz] | 330 |
| SFECF10M7FF00S0-R0 | - | 10.700 | fn±65 min. | 630 max. | 7.0max. [at fn] | 1.0 max. | 30 min. [within 9MHz to fn] | 25 min. [within fn to 12MHz] | 330 |
| SFECF10M7EA00S0-R0 | 10.700 ±30kHz | - | 330 ±50kHz | 700 max. | 3.0±2.0dB | 1.0 max. | 30 min. [within 9MHz to fo] | 30 min. [within fo to 12MHz] | 330 |
| SFECF10M7DF00S0-R0 | - | 10.700 | fn±145 min. | 990 max. | 6.0max. [at fn] | 3.0 max. | 20 min. [within 9MHz to fn] | 20 min. [within fn to 12MHz] | 330 |

Area of Attenuation: [within 20dB]

Area of Insertion Loss: at minimum loss point

Area of Ripple: within 3dB B.W.

Center frequency (fo) defined by the center of 3dB bandwidth.

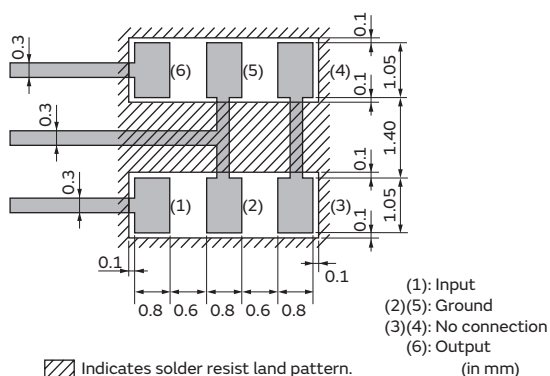
For safety purposes, connect the output of filters to the IF amplifier through a D.C. blocking capacitor. Avoid applying a direct current to the output of ceramic filters.

The order quantity should be an integral multiple of the "Minimum Quantity" shown in the packaging page.

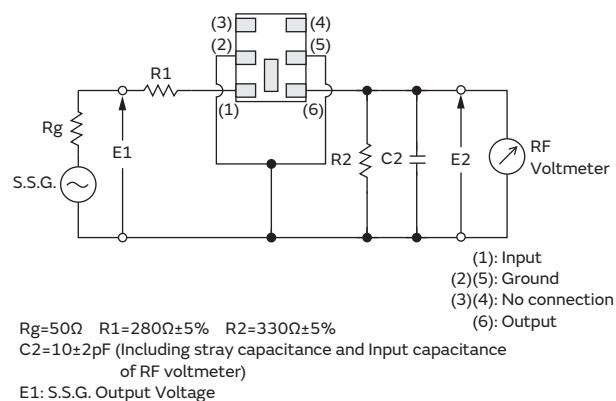
Standard Center Frequency Rank Code

| CODE | 30kHz Step | 25kHz Step |
|------|-----------------|-----------------|
| A | 10.700MHz±30kHz | 10.700MHz±25kHz |

Standard Land Pattern Dimensions

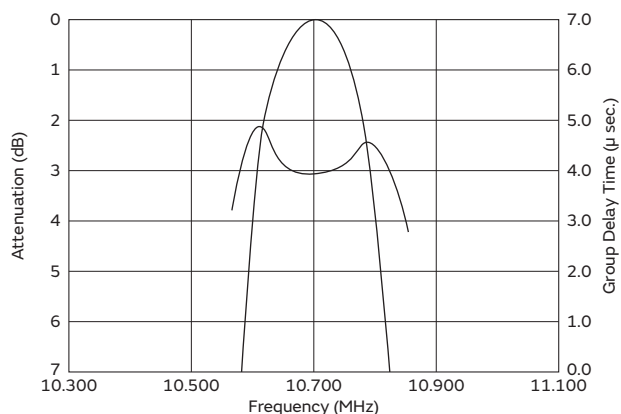


Test Circuit

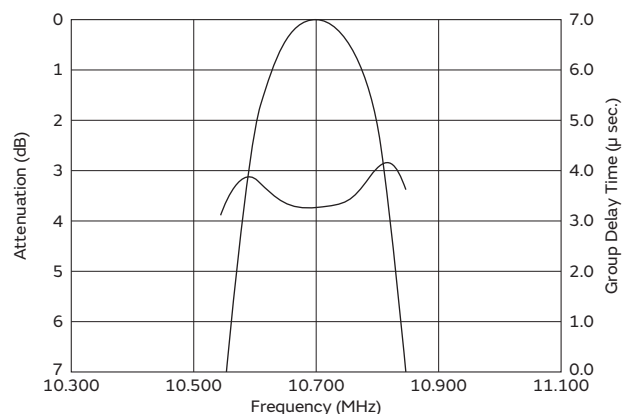


Frequency Characteristics Standard Type

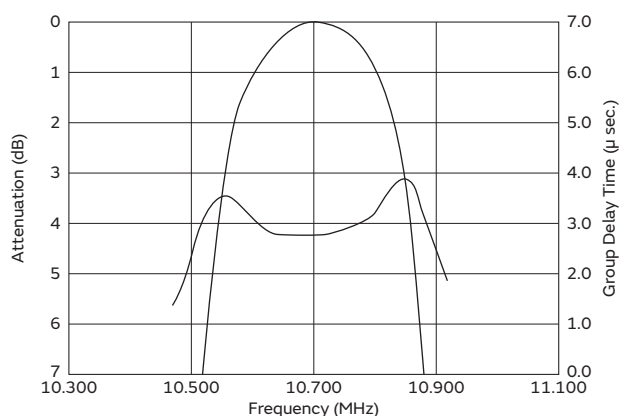
SFECF10M7HA00-R0/SFECF10M7HF00-R0



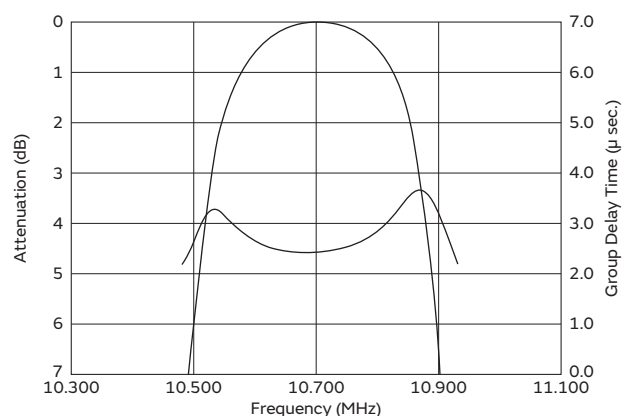
SFECF10M7GA00-R0/SFECF10M7GF00-R0



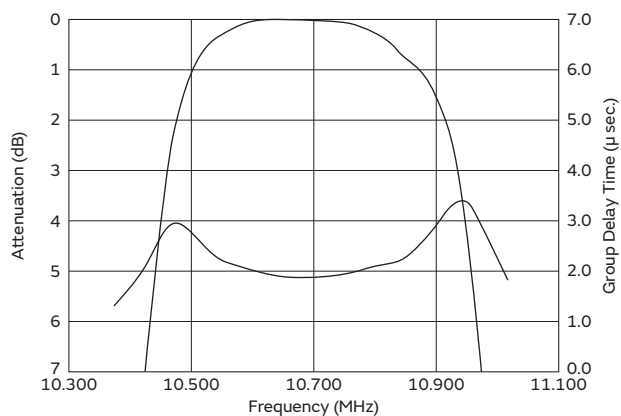
SFECF10M7FA00-R0/SFECF10M7FF00-R0



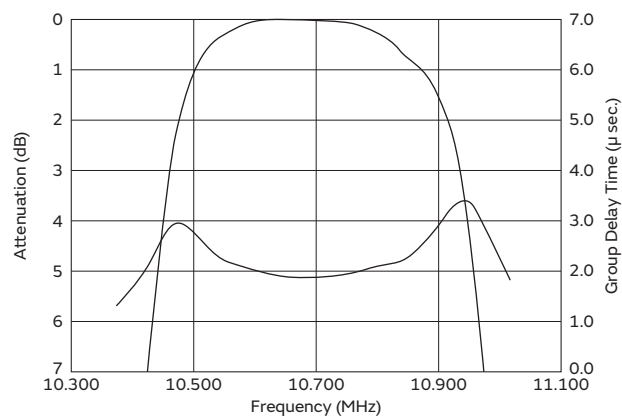
SFECF10M7EA00-R0



SFECF10M7DA0001-R0

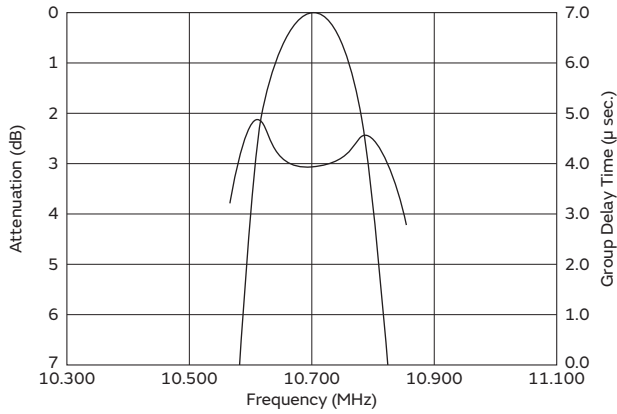


SFECF10M7DF00-R0

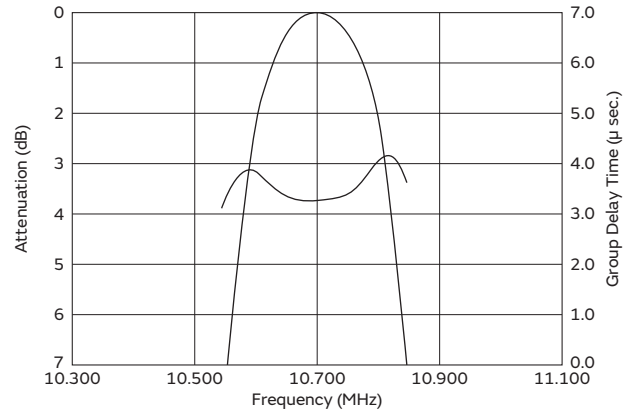


Frequency Characteristics High-reliability Type

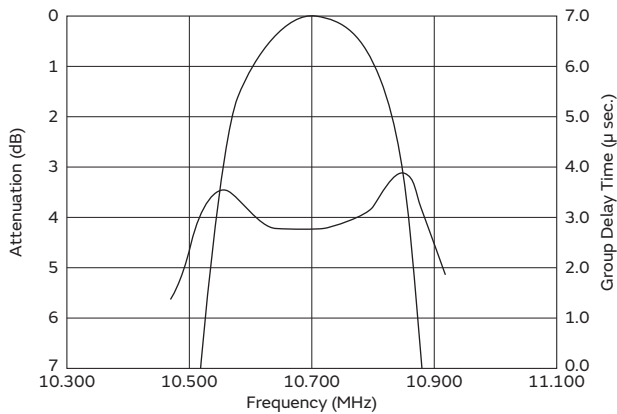
SFECF10M7HA00S0-R0/SFECF10M7HF00S0-R0



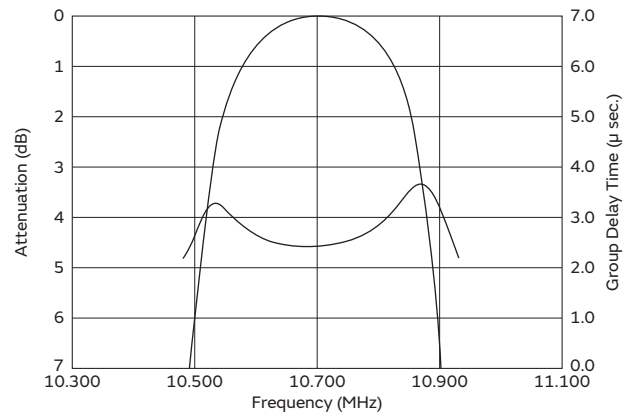
SFECF10M7GA00S0-R0/SFECF10M7GF00S0-R0



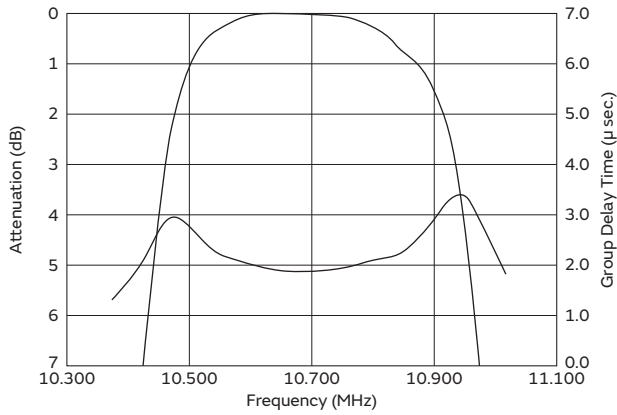
SFECF10M7FA00S0-R0/SFECF10M7FF00S0-R0



SFECF10M7EA00S0-R0

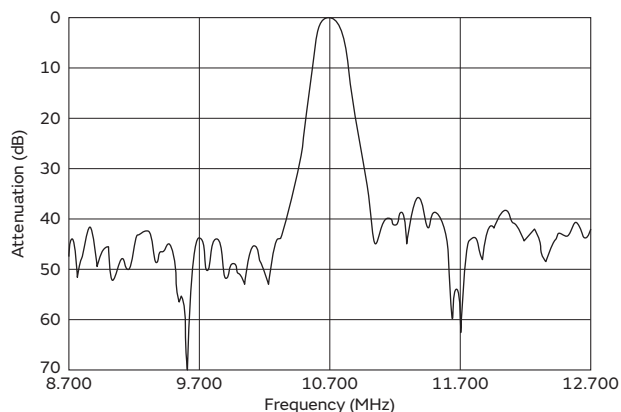


SFECF10M7DF00S0-R0

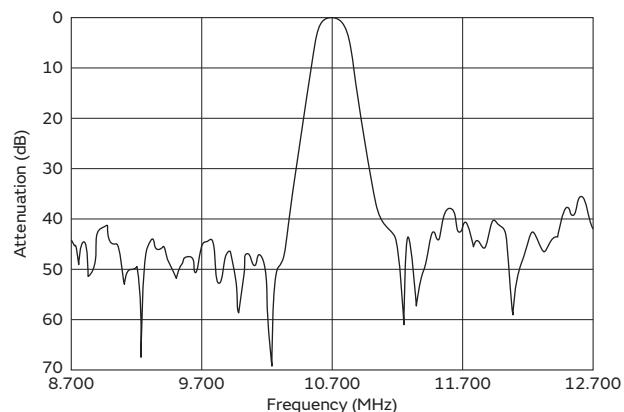


Frequency Characteristics (Spurious) Standard Type

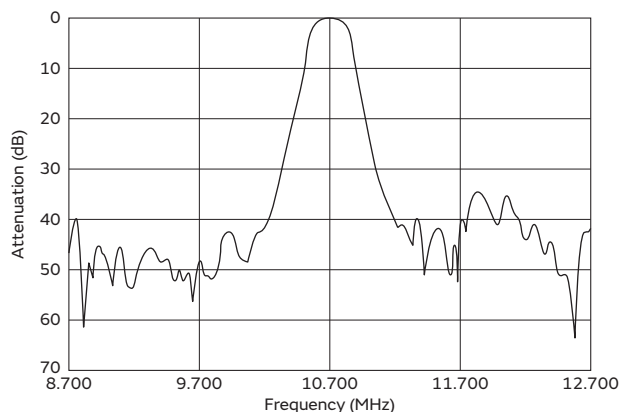
SFECF10M7HA00-R0/SFECF10M7HF00-R0



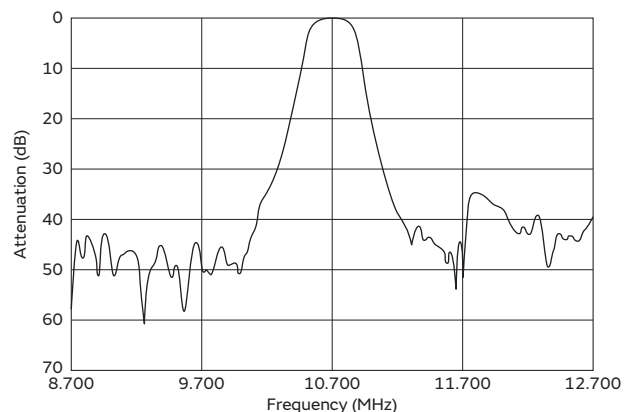
SFECF10M7GA00-R0/SFECF10M7GF00-R0



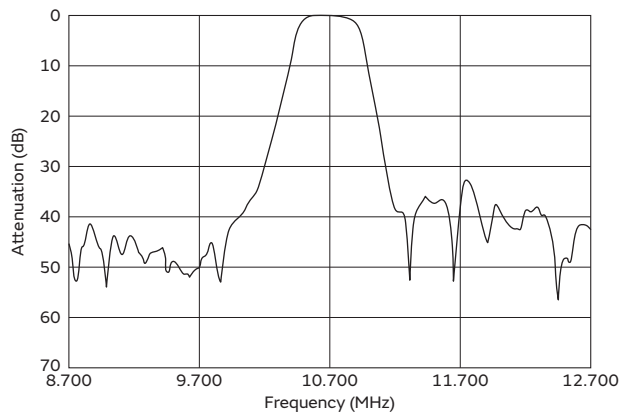
SFECF10M7FA00-R0/SFECF10M7FF00-R0



SFECF10M7EA00-R0

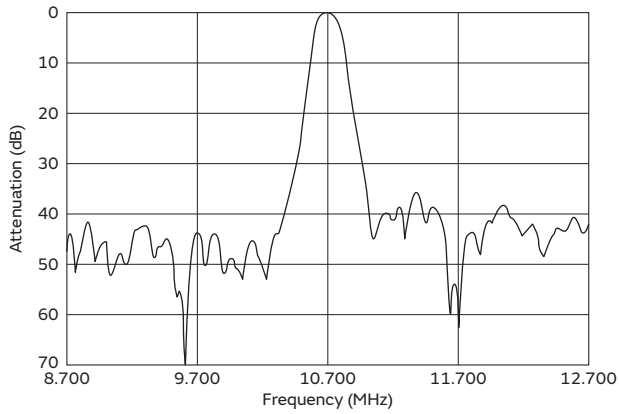


SFECF10M7DA0001-R0/SFECF10M7DF00-R0

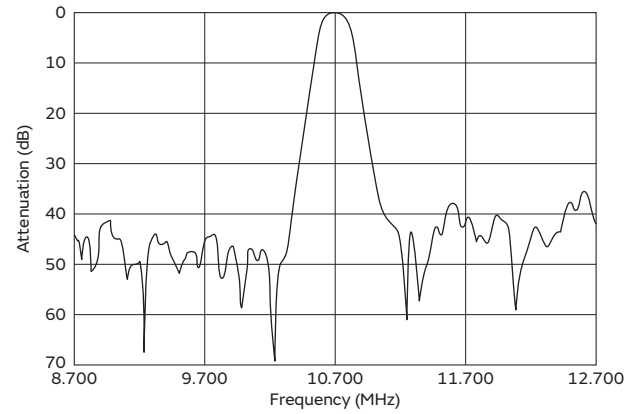


Frequency Characteristics (Spurious) High-reliability Type

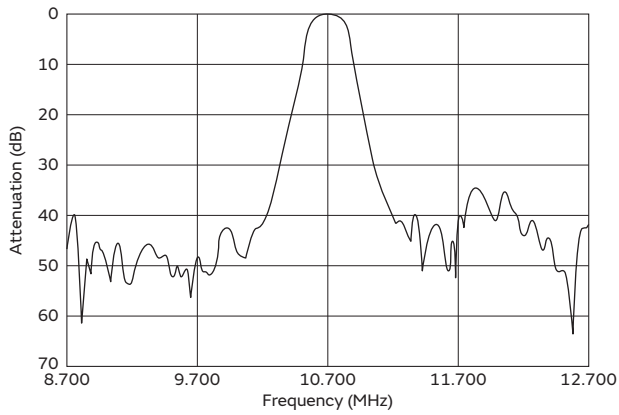
SFECF10M7HA00S0-R0/SFECF10M7HF00S0-R0



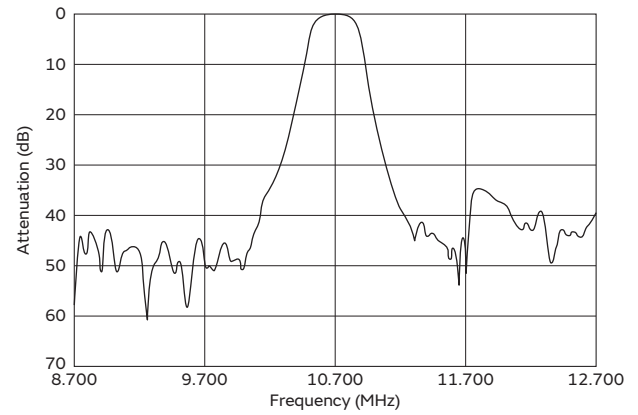
SFECF10M7GA00S0-R0/SFECF10M7GF00S0-R0



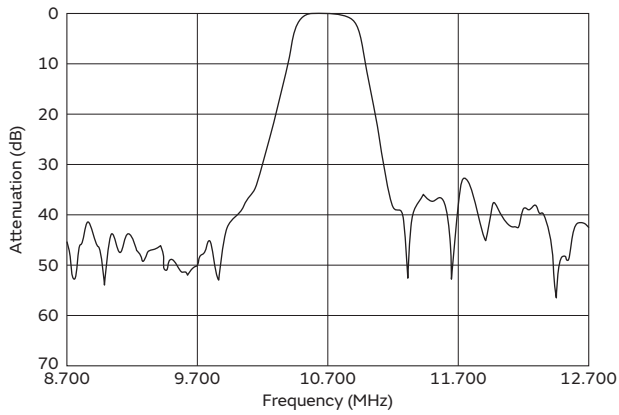
SFECF10M7FA00S0-R0/SFECF10M7FF00S0-R0



SFECF10M7EA00S0-R0



SFECF10M7DF00S0-R0



Notice

1

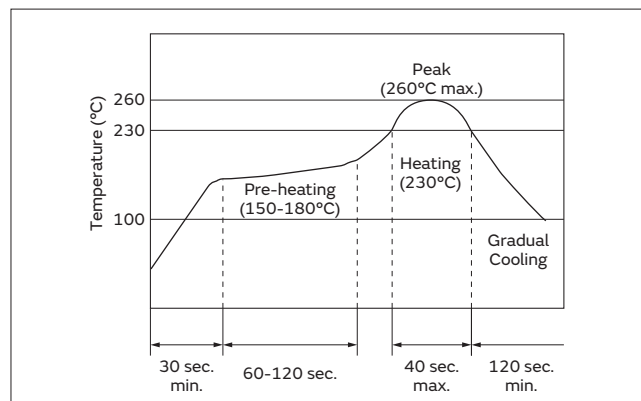
Ceramic Filters (CERAFIL) Chip Type SFECF Series

— Soldering and Mounting —

1. Standard Reflow Soldering Conditions

(1) Reflow

Filter is soldered twice within the following temperature conditions.



(2) Soldering Iron

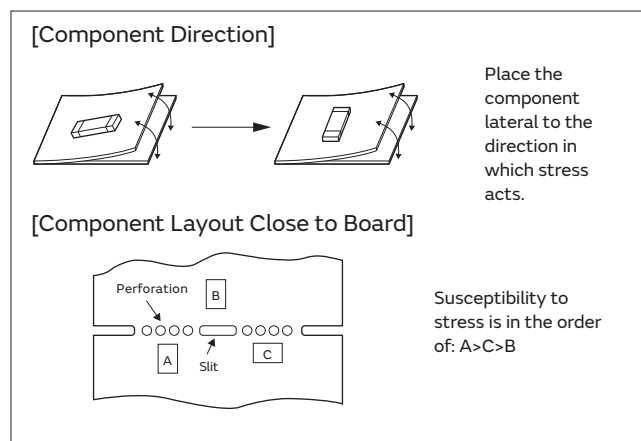
Filter is soldered at $+350\pm5^{\circ}\text{C}$ for 3.0 ± 0.5 seconds. The soldering iron should not touch the filter while soldering.

(3) Conditions for Placement Machines

The component is recommended for use with placement machines that employ optical placement capabilities. The component might be damaged by excessive mechanical force. Please make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines that utilize mechanical positioning. Please contact Murata for details beforehand.

(4) Other

- The component may be damaged if excess mechanical stress is applied to it mounted on the printed circuit board.
- Design layout of components on the PC board to minimize the stress imposed on the warp or flexure of the board.
- After installing components, if solder is excessively applied to the circuit board, mechanical stress will cause destruction resistance characteristics to degrade. To prevent this, be extremely careful in determining shape and dimension before designing the circuit board diagram.
- When the positioning claws and pick-up nozzle are worn, the load is applied to the components while positioning is concentrated on positioning accuracy, etc. Careful checking and maintenance are necessary to prevent unexpected trouble.
- When correcting components with a soldering iron, the tip of the soldering iron should not directly touch the component. Depending on the soldering conditions, the effective area of terminations may be reduced. Solder containing Ag should be used to prevent electrode erosion.
- Do not use strong acidity flux, more than 0.2wt% chlorine content, in reflow soldering.



Continued on the following page. ↗

Notice

Continued from the preceding page. ↘

2. Wash

Do not clean or wash the component as it is not hermetically sealed.

3. Coating

In case of overcoating the component, conditions such as material of resin, cure temperature, and so on should be evaluated well.

— Storage and Operating Conditions —

1. Product Storage Conditions

Please store the products in a room where the temperature/humidity is stable, and avoid places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to +40°C

Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because solderability may be degraded due to storage under poor conditions.

Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

(1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because quality and solderability may be degraded due to storage in a chemical atmosphere.

(2) Please do not put the products directly on the floor without anything under them to avoid damp places and/or dusty places.

(3) Please do not store the products in places such as a damp heated place or any place exposed to direct sunlight or excessive vibration.

(4) Please use the products immediately after package is opened, because quality and solderability may be degraded due to storage under poor conditions.

(5) To avoid cracking of the ceramic element, please do not drop the products.

4. Other

Please be sure to consult with our sales representative or engineer whenever the products are to be used in conditions not listed above.

— Rating —

The component may be damaged if excessive mechanical stress is applied.

— Handling —

1. Accurate test circuit values are required to measure electrical characteristics. Misrelation may be caused if there is any deviation, especially stray capacitance, from the test circuit in the specification.

2. The components, packed in a moisture proof bag (dry pack), are sensitive to moisture. The following treatment is required before applying reflow soldering, to avoid reliability degradation caused by thermal stress. When unpacked, store the component in an atmosphere of reflow 30°C and below 60%R.H., and solder within 1 week.

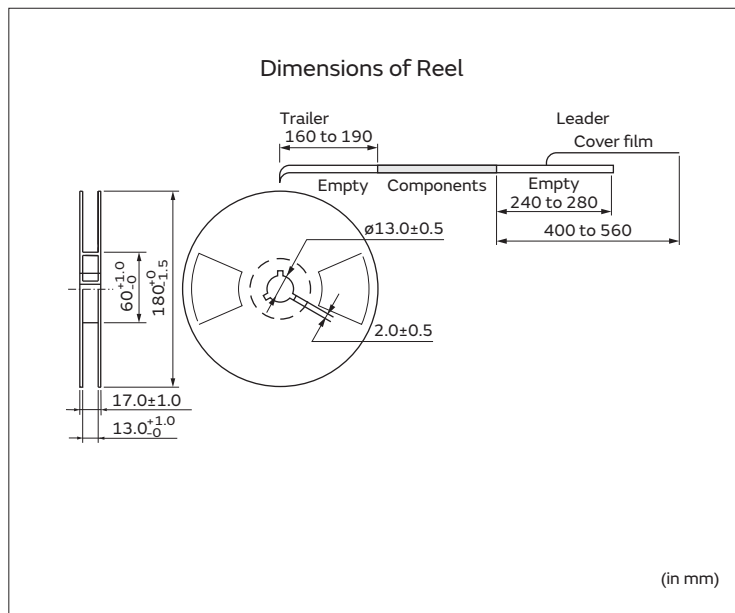
Packaging

Minimum Quantity/Dimensions of Reel

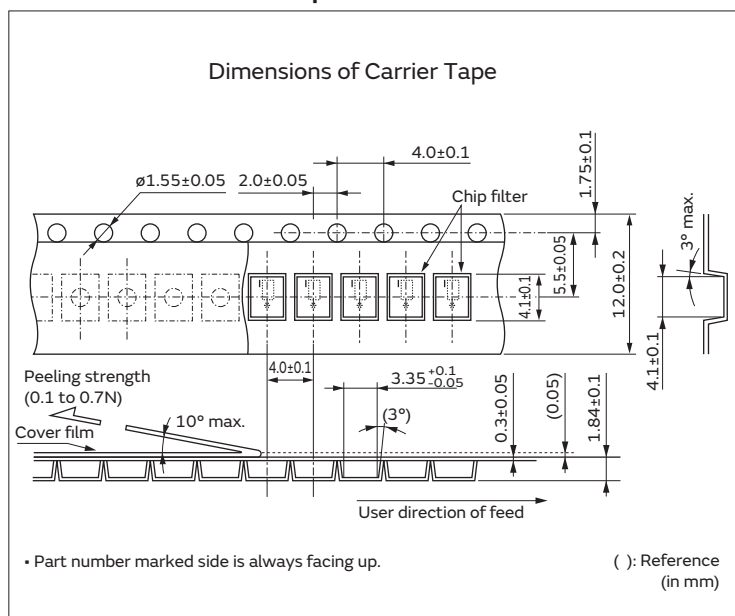
Embossed Tape ø180mm

2,000

(pcs.)



Dimensions of Carrier Tape



Ceramic Filters (CERAFIL)

Chip Type SFECV/SFECK Series

RoHS

The SFECV/SFECK10M7 series for FM receivers are monolithic type ceramic filters that utilize the thickness expander mode of piezoelectric ceramics. The SFECV series enable customers to make an AM/FM set very thin, and it can be useful to the total chip circuit.

Features

1. The piezoelectric element is sandwiched by heat resistant substrate, thus it has excellent mechanical strength, and it is suitable for automatic mounting.
2. Various bandwidths are available. Select a suitable type in accordance with the desired characteristics.
3. Operating Temperature Range:
-20 to +80°C (Standard Type)
-40 to +85°C (High-reliability Type)
Storage Temperature Range:
-40 to +85°C (Standard Type)
-55 to +85°C (High-reliability Type)

Applications

1. Small, thin radios
2. Automotive radios
3. Headphone stereos

Standard Type

| Part Number | Center Frequency (fo) (MHz) | 3dB Bandwidth (kHz) | Attenuation (kHz) | Insertion Loss (dB) | Ripple (dB) | Spurious Attenuation (1) (dB) | Spurious Attenuation (2) (dB) | Input/Output Impedance (ohm) |
|--------------------|-----------------------------|---------------------|-------------------|---------------------|-------------|---------------------------------|---------------------------------|------------------------------|
| SFECV15M0EQ0001-R0 | 15.000 ±50kHz | 300 min. | 750 max. | 7.0max. | 1.0 max. | 30 min. [within 14MHz to fo] | 30 min. [within fo to 16MHz] | 330 |
| SFECV10M7KA00-R0 | 10.700 ±30kHz | 110 ±30kHz | 320 max. | 6.0±2.0dB | 1.0 max. | 35 min. [within 9MHz to fo] | 35 min. [within fo to 12MHz] | 330 |
| SFECV10M7JA00-R0 | 10.700 ±30kHz | 150 ±40kHz | 380 max. | 5.5±2.0dB | 1.0 max. | 35 min. [within 9MHz to fo] | 35 min. [within fo to 12MHz] | 330 |

Area of Attenuation: [within 20dB]

Area of Insertion Loss: at minimum loss point

Center frequency (fo) defined by the center of 3dB bandwidth.

For safety purposes, connect the output of filters to the IF amplifier through a D.C. blocking capacitor. Avoid applying a direct current to the output of ceramic filters.

The order quantity should be an integral multiple of the "Minimum Quantity" shown in the packaging page.

High-reliability Type

| Part Number | Center Frequency (fo) (MHz) | 3dB Bandwidth (kHz) | Attenuation (kHz) | Insertion Loss (dB) | Ripple (dB) | Spurious Attenuation (1) (dB) | Spurious Attenuation (2) (dB) | Input/Output Impedance (ohm) |
|--------------------|-----------------------------|---------------------|-------------------|---------------------|-------------|--------------------------------|---------------------------------|------------------------------|
| SFECK10M7KA00S0-R0 | 10.700 ±30kHz | 110 ±30kHz | 320 max. | 6.0±2.0dB | 1.0 max. | 35 min. [within 9MHz to fo] | 35 min. [within fo to 12MHz] | 330 |
| SFECK10M7JA00S0-R0 | 10.700 ±30kHz | 150 ±40kHz | 380 max. | 5.5±2.0dB | 1.0 max. | 35 min. [within 9MHz to fo] | 35 min. [within fo to 12MHz] | 330 |

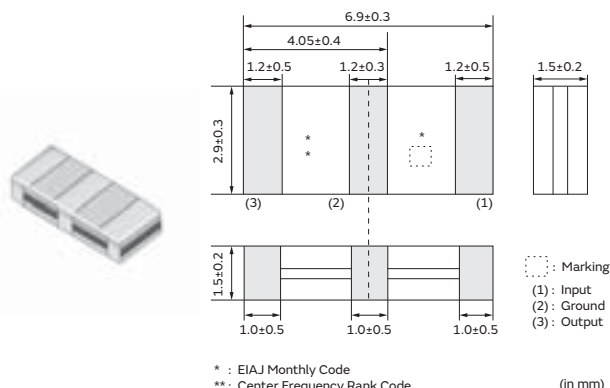
Area of Attenuation: [within 20dB]

Area of Insertion Loss: at minimum loss point

Center frequency (fo) defined by the center of 3dB bandwidth.

For safety purposes, connect the output of filters to the IF amplifier through a D.C. blocking capacitor. Avoid applying a direct current to the output of ceramic filters.

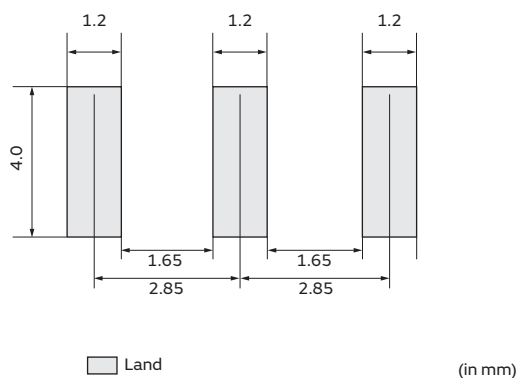
The order quantity should be an integral multiple of the "Minimum Quantity" shown in the packaging page.



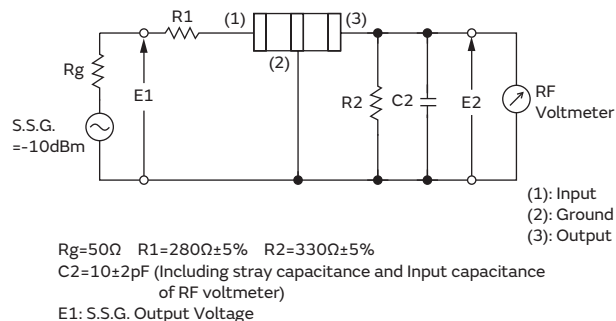
Standard Center Frequency Rank Code

| CODE | 30kHz Step | 25kHz Step |
|------|-----------------|-----------------|
| A | 10.700MHz±30kHz | 10.700MHz±25kHz |

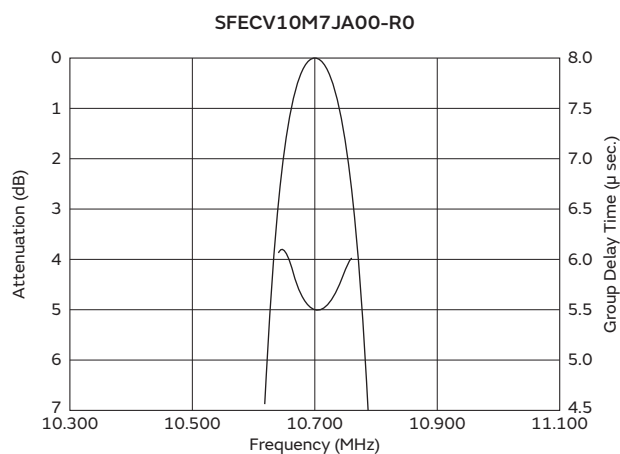
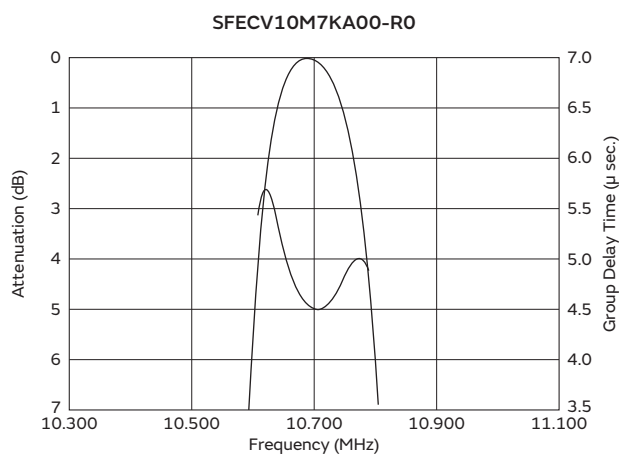
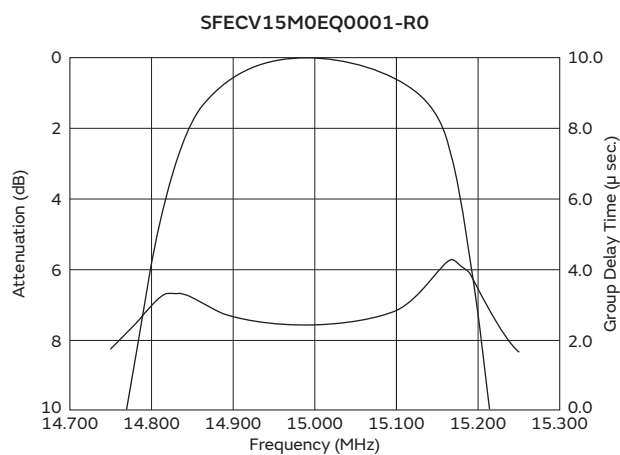
Standard Land Pattern Dimensions



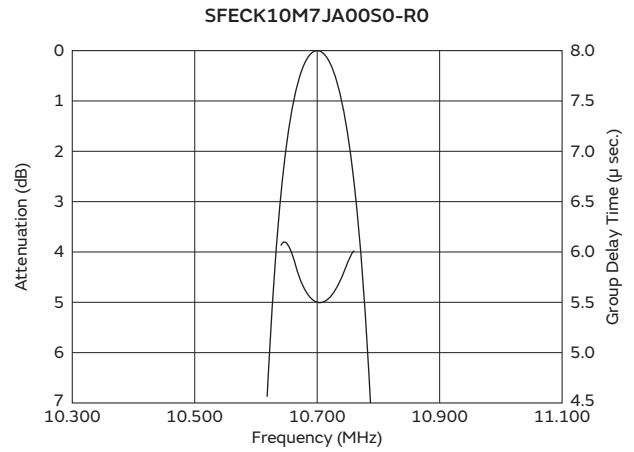
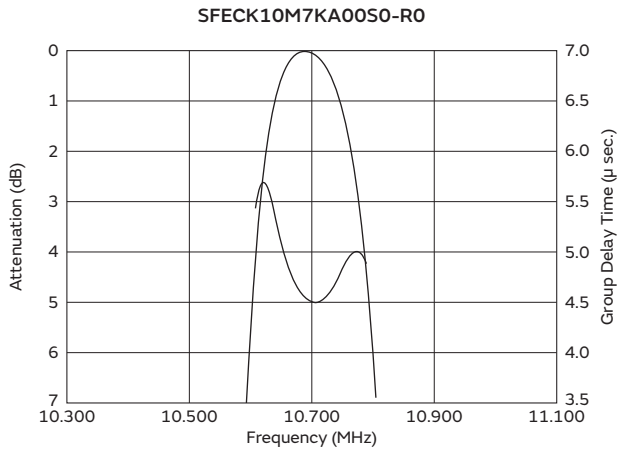
Test Circuit



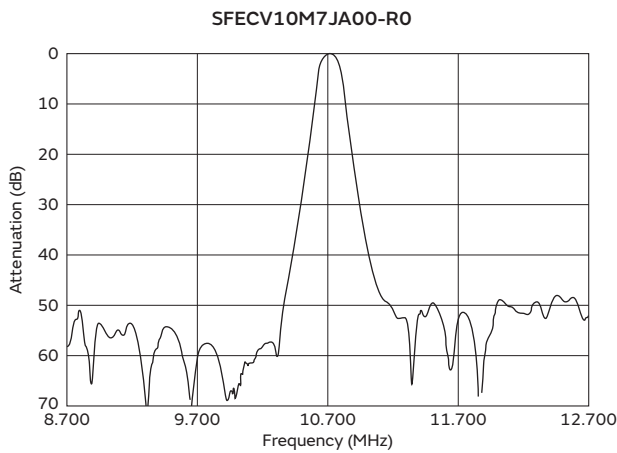
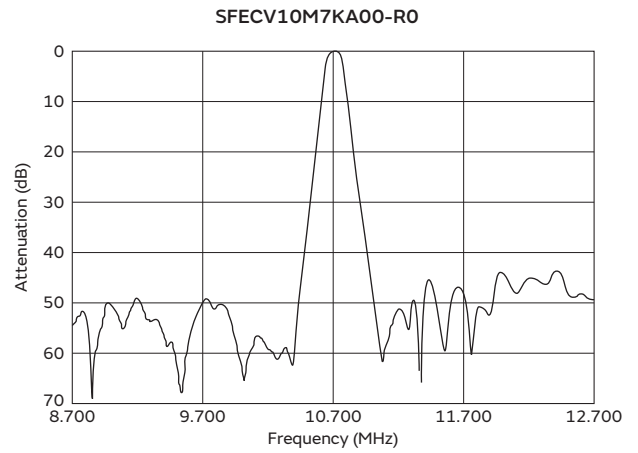
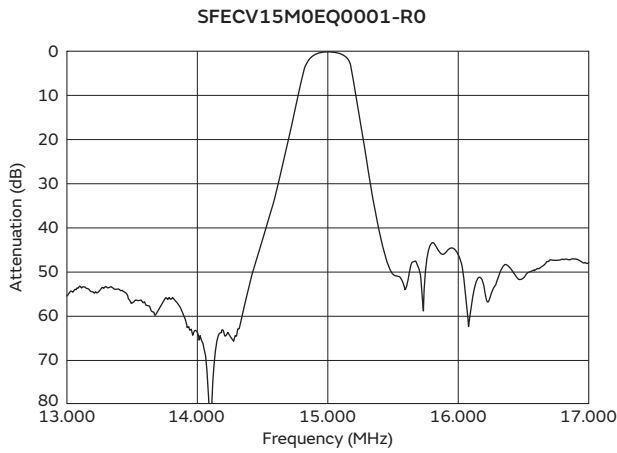
Frequency Characteristics Standard Type



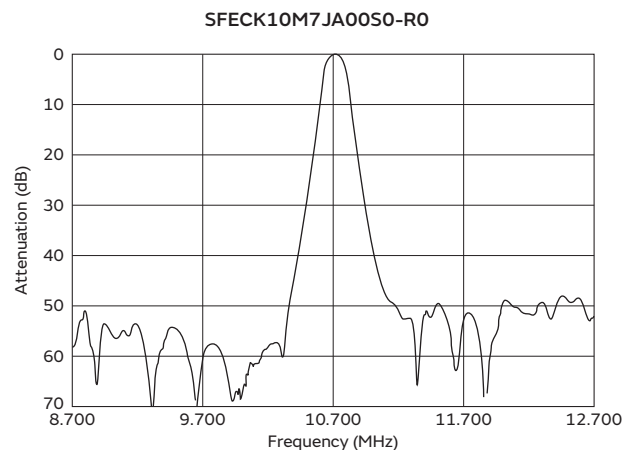
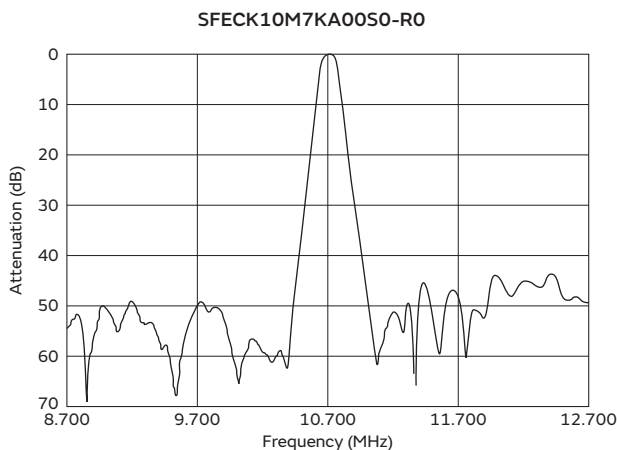
Frequency Characteristics High-reliability Type



Frequency Characteristics (Spurious) Standard Type



Frequency Characteristics (Spurious) High-reliability Type



Notice

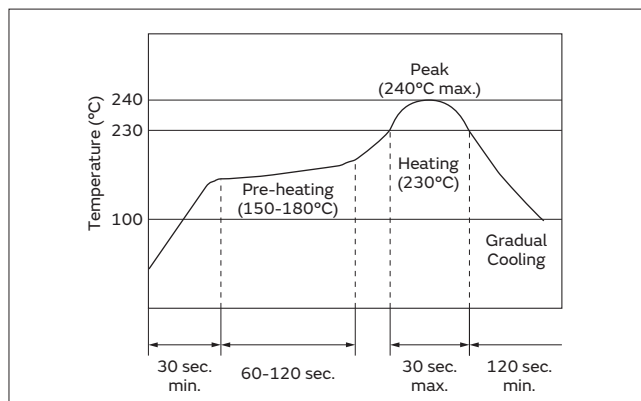
Ceramic Filters (CERAFIL) Chip Type SFECV/SFECK Series

— Soldering and Mounting —

1. Standard Reflow Soldering Conditions

(1) Reflow

Filter is soldered twice within the following temperature conditions.



(2) Soldering Iron

Filter is soldered at $+350 \pm 5^\circ\text{C}$ for 3.0 ± 0.5 seconds. The soldering iron should not touch the filter while soldering.

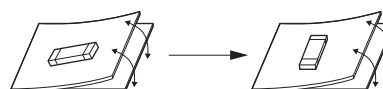
(3) Conditions for Placement Machines

The component is recommended for use with placement machines that employ optical placement capabilities. Damage may result from excessive mechanical force. Please make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines that utilize mechanical positioning. Please contact Murata for details beforehand.

(4) Other

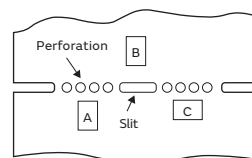
- The component may be damaged if excess mechanical stress is applied to it mounted on the printed circuit board.
- Design layout of components on the PC board to minimize the stress imposed on the warp or flexure of the board.
- After installing components, if solder is excessively applied to the circuit board, mechanical stress will cause destruction resistance characteristics to degrade. To prevent this, be extremely careful in determining shape and dimension before designing the circuit board diagram.
- When the positioning claws and pick-up nozzle are worn, the load is applied to the components while positioning is concentrated to one positioning accuracy, etc. Careful checking and maintenance are necessary to prevent unexpected trouble.
- When correcting components with a soldering iron, the tip of the soldering iron should not directly touch the component. Depending on the soldering conditions, the effective area of terminations may be reduced. Solder containing Ag should be used to prevent electrode erosion.
- Do not use strong acidity flux, more than 0.2wt% chlorine content, in reflow soldering.

[Component Direction]



Put the component laterally to the direction in which stress acts.

[Component Layout Close to Board]



Susceptibility to stress is in the order of: A > C > B

Continued on the following page. ↗

Notice

Continued from the preceding page. ↘

2. Wash

Do not clean or wash the component as it is not hermetically sealed.

3. Coating

In case of overcoating the component, conditions such as material of resin, cure temperature, and so on should be evaluated well.

— Storage and Operating Conditions —

1. Product Storage Conditions

Please store the products in room where the temperature/humidity is stable, and avoid places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to +40°C

Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (Shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the products may be degraded in solderability due to storage under poor conditions.

Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

(1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because quality and solderability may be degraded due to the storage in a chemical atmosphere.

(2) Please do not put the products directly on the floor without anything under them to avoid damp places and/or dusty places.

(3) Please do not store the products in the places such as a damp heated place or any place exposed to direct sunlight or excessive vibration.

(4) Please use the products immediately after package is opened, because quality and solderability may be degraded due to storage under the poor conditions.

(5) To avoid cracking of the ceramic element, please do not drop the products.

4. Other

Please be sure to consult with our sales representative or engineer whenever the products are to be used in conditions not listed above.

— Rating —

The component may be damaged if excessive mechanical stress is applied.

— Handling —

Accurate test circuit values are required to measure electrical characteristics.

Miscorrelation may be caused if there is any deviation, especially stray capacitance, from the test circuit in the specification.

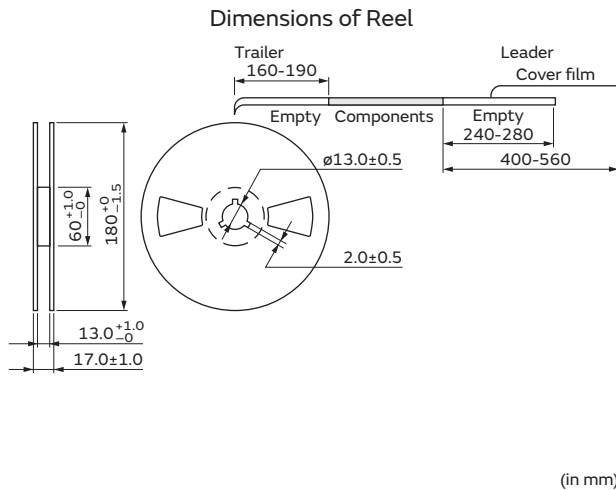
Packaging

Minimum Quantity/Dimensions of Reel

Embossed Tape $\phi 180\text{mm}$

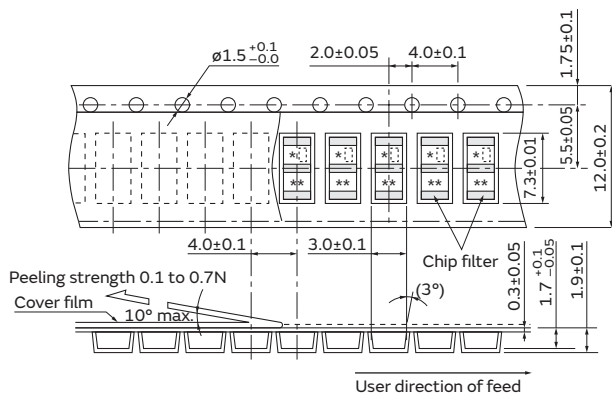
2,000

(pcs.)



Dimensions of Carrier Tape

Dimensions of Carrier Tape



• Part number marked side is always facing up.

() : Reference
(in mm)

Ceramic Discriminator (CERAFIL)

Chip Type CDSCB Series

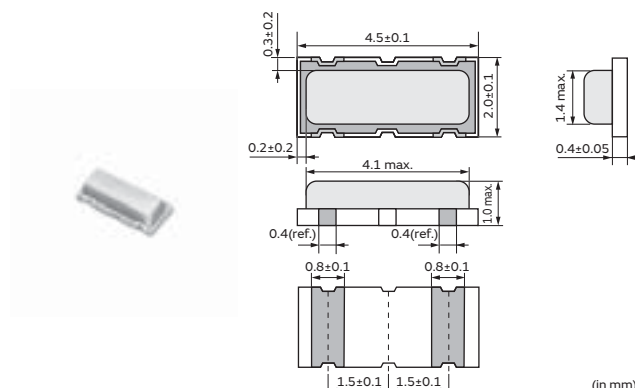
RoHS

The CDSCB10M7 series forms a resonator on a piezoelectric ceramic substrate. In combination with ICs, this type obtains stable demodulation characteristics in a wide bandwidth.

They have 1.0mm max. thickness and small mounting area (4.5x2.0mm).

Features

1. Compact and high reliability and recommended for automotive applications.
2. Can be combined with various ICs. The IC is determined by the last number in the part number.
3. Stable demodulation characteristics can be obtained without adjustment.
4. Stable temperature characteristics.
5. Available lead (Pb) free solder reflow.



| Part Number | Center Frequency (fo) (MHz) | Recovered Audio 3dB BW (kHz) | Recovered Audio Output (mV) | Distortion (%) | S Curve (mV) | IC |
|--------------------|-----------------------------|------------------------------|-----------------------------|----------------|--------------|-----------|
| CDSCB10M7GA105A-R0 | 10.700 ±30kHz | 220 min. | 110 min. | 1.5 max. | - | TEA5757HL |
| CDSCB10M7GA113-R0 | 10.700 ±30kHz | 300 min. | 110 min. | 1.0 max. | - | TA2154FN |
| CDSCB10M7GA119-R0 | 10.700 ±30kHz | 500 min. | 75 min. | 1.0 max. | - | TRF6901 |
| CDSCB10M7GA121-R0 | 10.700 ±30kHz | 390 min. | 80 min. | 1.0 max. | - | LV23100V |
| CDSCB10M7GA135-R0 | 10.700 ±30kHz | 155 min. | 75 min. | - | - | TH71101 |
| CDSCB10M7GA136-R0 | 10.700 ±30kHz | 140 min. | 120 min. | - | - | TH7122 |
| CDSCB10M7GF072-R0 | 10.700 (fn) | fn±150 min. | 130 min. | 2.0 max. | - | TA31161 |
| CDSCB10M7GF107S-R0 | 10.700 (fn) | fn±80 min. | 52 min. | 3.0 max. | - | TA31272FN |
| CDSCB10M7GF109-R0 | 10.700 (fn) | fn±100 min. | 170 min. | 3.0 max. | - | TK14588V |
| CDSCB10M7GF123-R0 | 10.700 (fn) | - | - | - | 900 min. | TA31275FN |
| CDSCB10M7GF123S-R0 | 10.700 (fn) | - | - | - | 900 min. | TA31275FN |
| CDSCB10M7GF126-R0 | 10.700 (fn) | - | - | - | 400 min. | NJM2295AV |

(fn) indicates nominal center frequency (10.700MHz).

For safety purposes, avoid applying a direct current between the terminals.

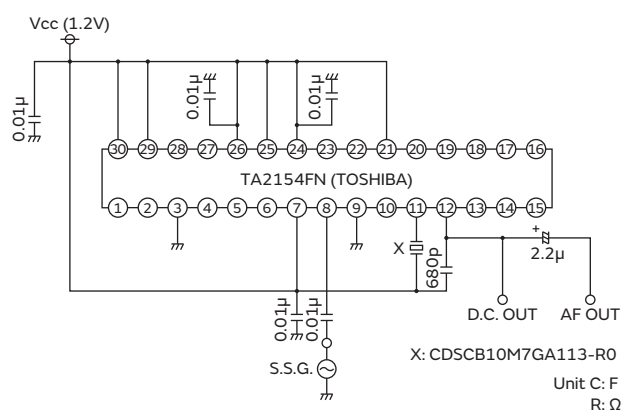
The order quantity should be an integral multiple of the "Minimum Quantity" shown in the packaging page.

Standard Center Frequency Rank Code

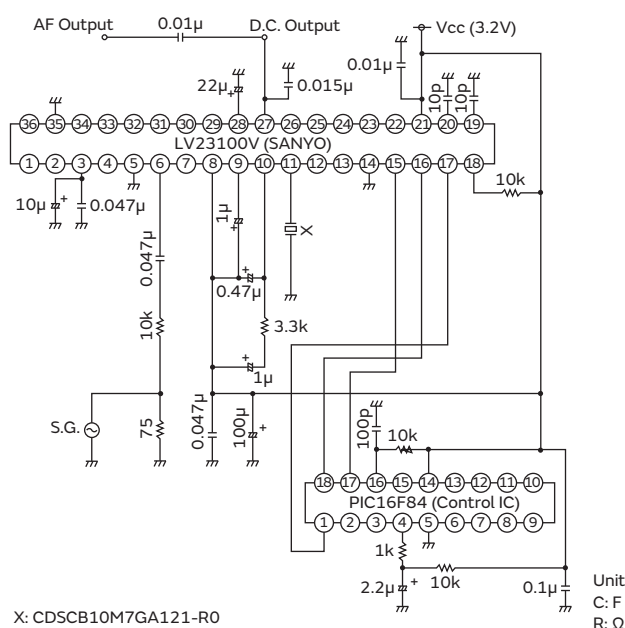
| CODE | 30kHz Step | 25kHz Step |
|------|-----------------|-----------------|
| A | 10.700MHz±30kHz | 10.700MHz±25kHz |



CDSCB10M7GA113-R0

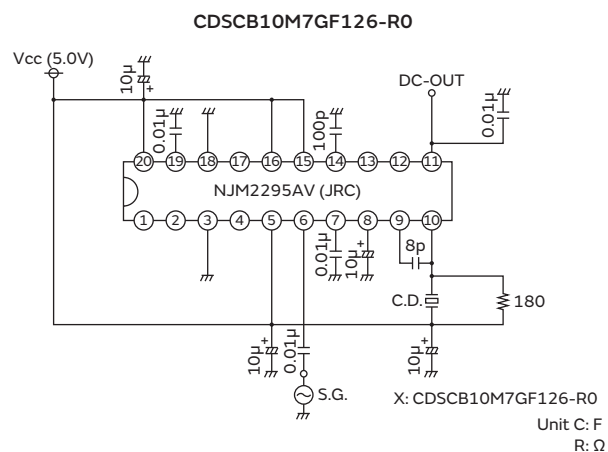
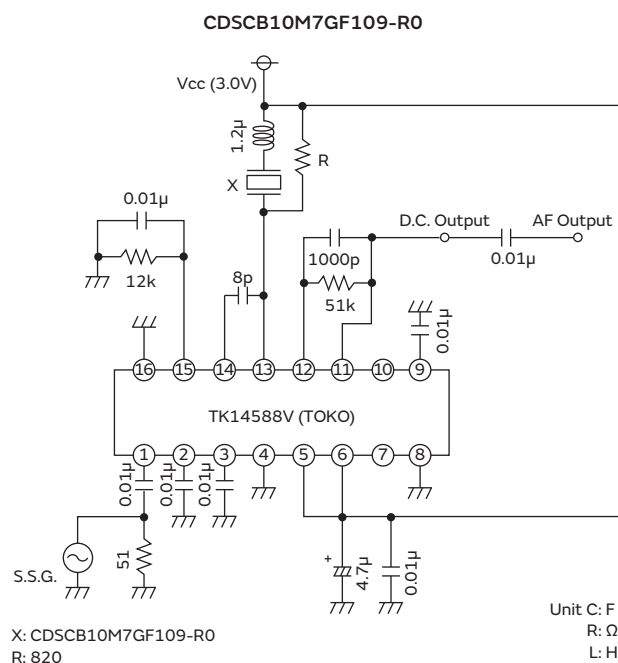
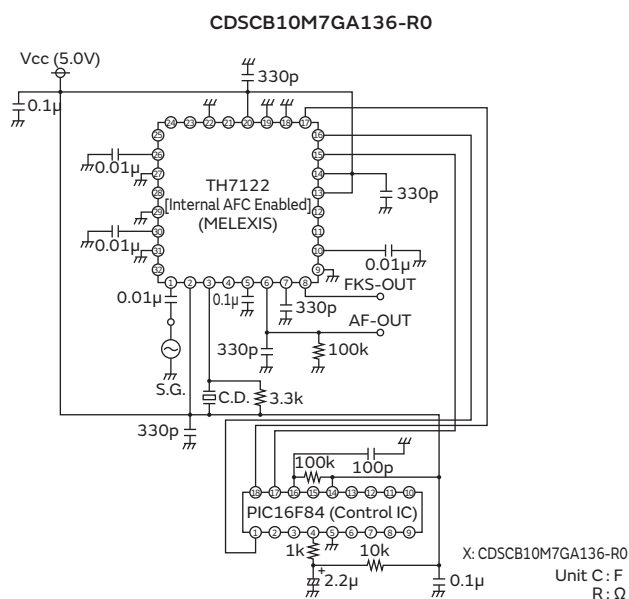


CDSCB10M7GA121-R0



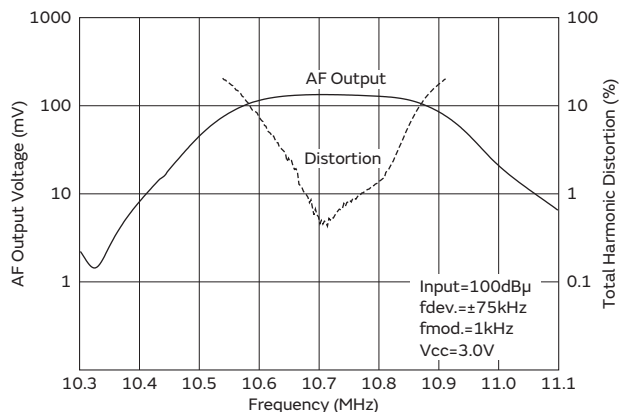
Continued on the following page. ↗

Test Circuit

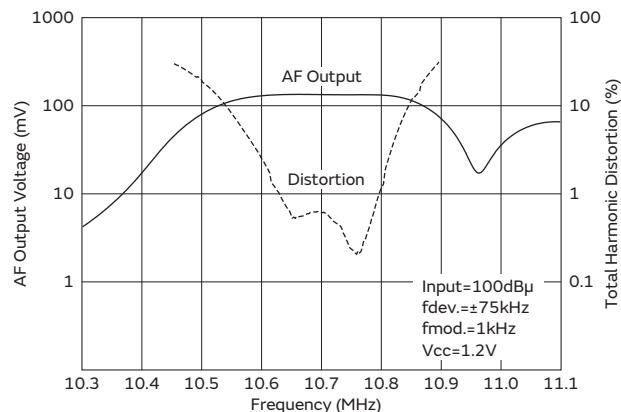


Recovered Audio Curve

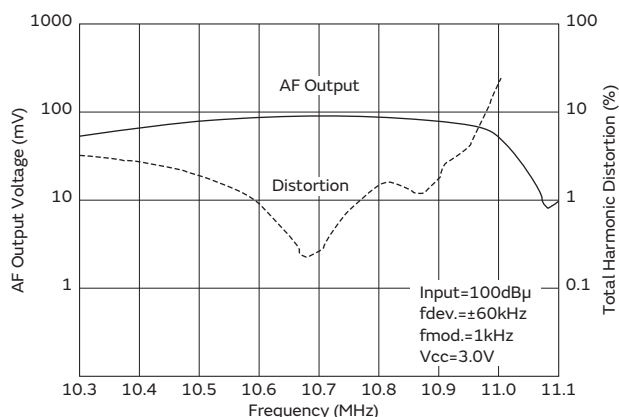
CDSCB10M7GA105A-R0



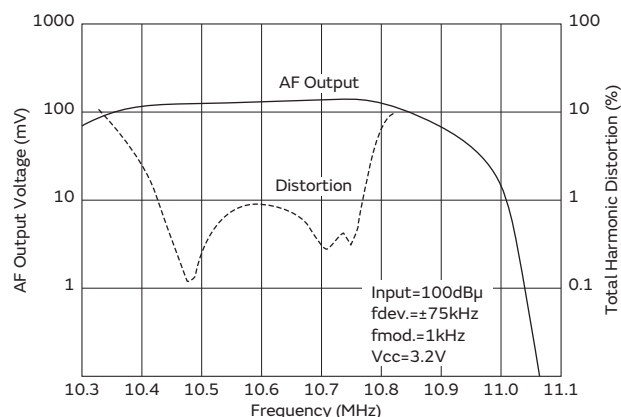
CDSCB10M7GA113-R0



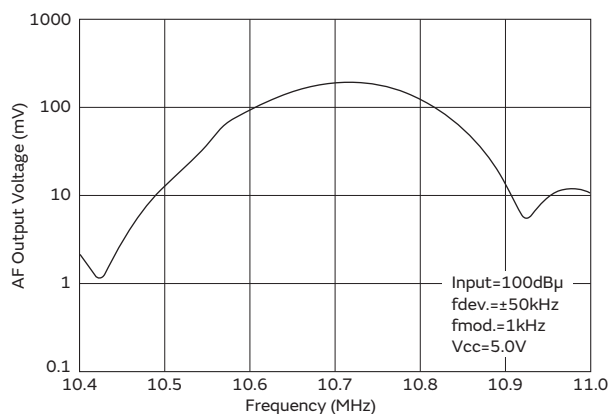
CDSCB10M7GA119-R0



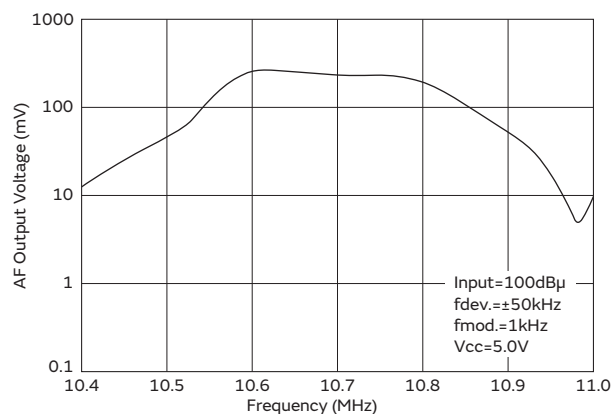
CDSCB10M7GA121-R0



CDSCB10M7GA135-R0



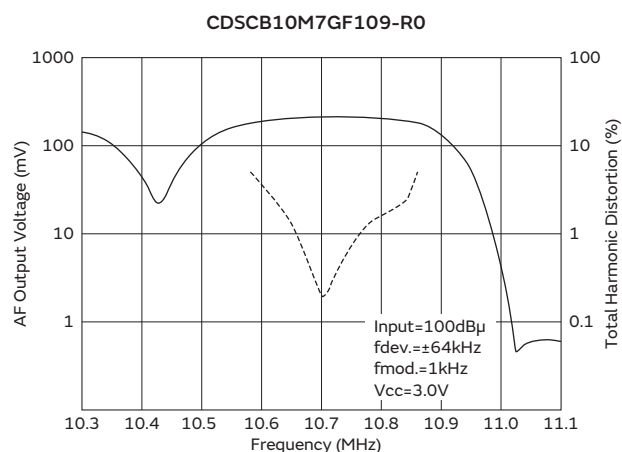
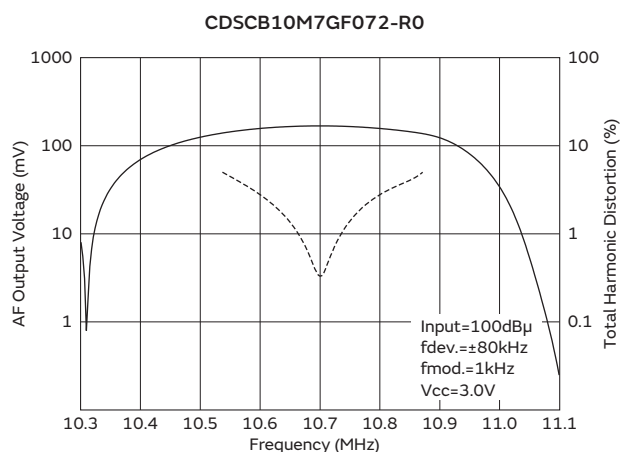
CDSCB10M7GA136-R0



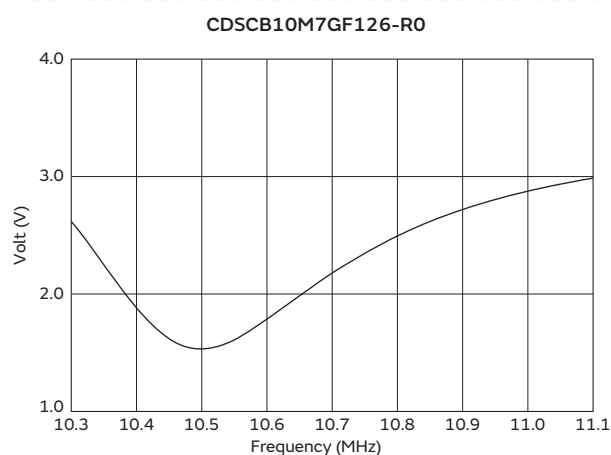
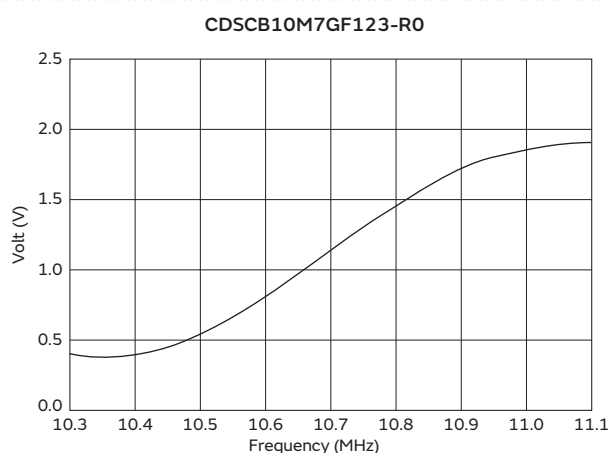
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Recovered Audio Curve



S Curve



Notice

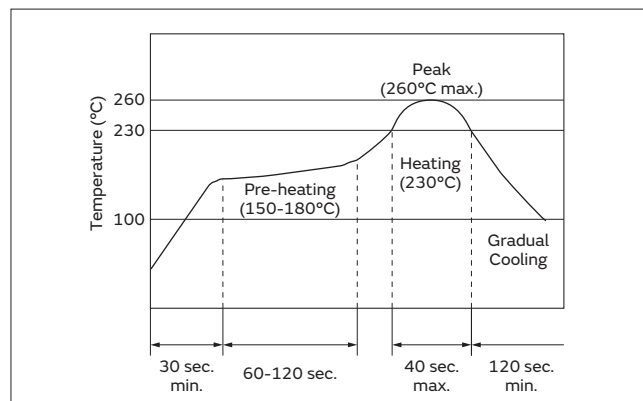
Ceramic Discriminator (CERAFIL) Chip Type CDSCB Series

— Soldering and Mounting —

1. Standard Reflow Soldering Conditions

(1) Reflow

Filter is soldered twice within the following temperature conditions.



(2) Soldering Iron

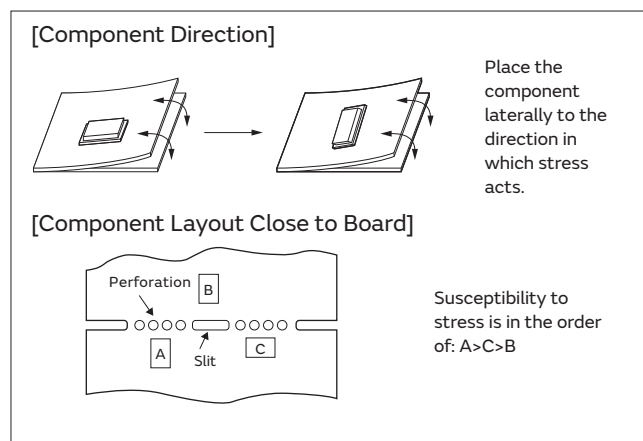
Filter is soldered at $+300\pm5^{\circ}\text{C}$ for 3.0 ± 0.5 seconds. The soldering iron should not touch the filter while soldering.

(3) Conditions for Placement Machines

The component is recommended for use with placement machines that employ optical placement capabilities. The component might be damaged by excessive mechanical force. Please make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines that utilize mechanical positioning. Please contact Murata for details beforehand.

(4) Other

- The component may be damaged if excess mechanical stress is applied to it mounted on the printed circuit board.
- Design layout of components on the PC board to minimize the stress imposed on the warp or flexure of the board.
- After installing components, if solder is excessively applied to the circuit board, mechanical stress will cause destruction resistance characteristics to degrade. To prevent this, be extremely careful in determining shape and dimension before designing the circuit board diagram.
- When the positioning claws and pick-up nozzle are worn, the load is applied to the components while positioning is concentrated on positioning accuracy, etc. Careful checking and maintenance are necessary to prevent unexpected trouble.
- When correcting components with a soldering iron, the tip of the soldering iron should not directly touch the component. Depending on the soldering conditions, the effective area of terminations may be reduced. Solder containing Ag should be used to prevent electrode erosion.



Continued on the following page. ↗

Notice

Continued from the preceding page. ↘

2. Wash

Do not clean or wash the component as it is not hermetically sealed.

3. Coating

In case of overcoating the component, conditions such as material of resin, cure temperature, and so on should be evaluated well.

— Storage and Operating Conditions —

1. Product Storage Conditions

Please store the products in a room where the temperature/humidity is stable, and avoid places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to +40°C

Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because solderability may be degraded due to storage under poor conditions.

Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

(1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because quality and solderability may be degraded due to storage in a chemical atmosphere.

(2) Please do not put the products directly on the floor

without anything under them to avoid damp places and/or dusty places.

(3) Please do not store the products in places such as a damp heated place or any place exposed to direct sunlight or excessive vibration.

(4) Please use the products immediately after package is opened, because quality and solderability may be degraded due to storage under poor conditions.

(5) To avoid cracking of the ceramic element, please do not drop the products.

4. Other

Please be sure to consult with our sales representative or engineer whenever the products are to be used in conditions not listed above.

— Rating —

The component may be damaged if excessive mechanical stress is applied.

— Handling —

Accurate test circuit values are required to measure electrical characteristics. Miscalculation may be caused if there is any deviation, especially stray capacitance, from the test circuit in the specification.

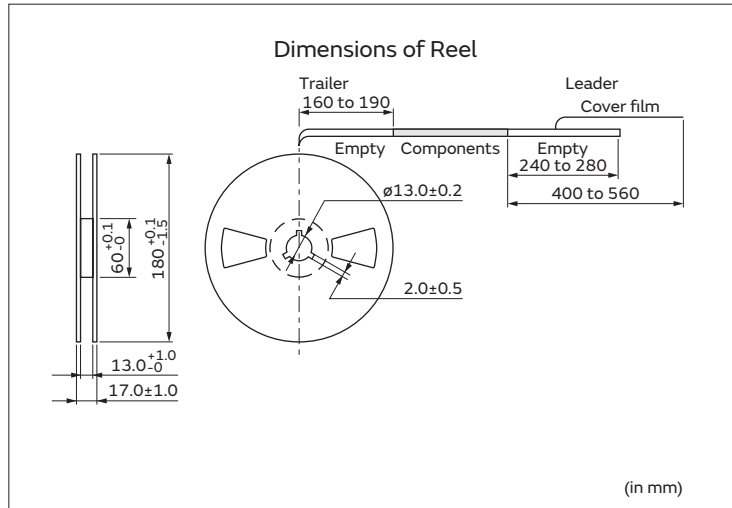
Packaging

Minimum Quantity/Dimensions of Reel

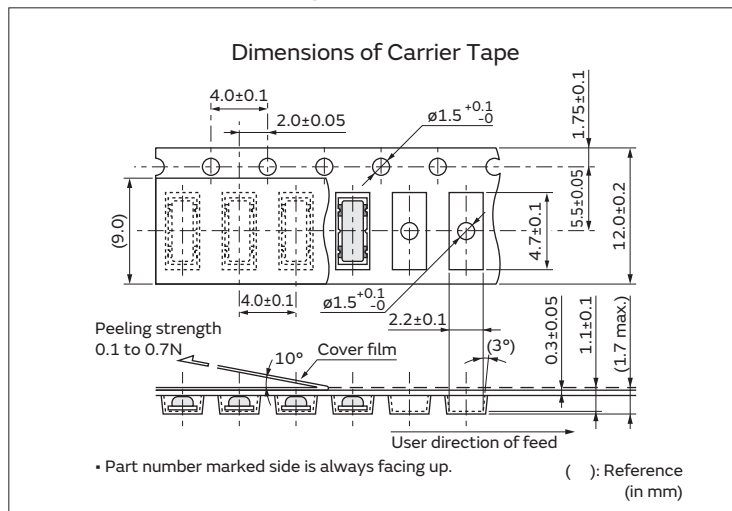
Embossed Tape $\phi 180\text{mm}$

2,000

(pcs.)



Dimensions of Carrier Tape



Crystal Filters

Chip Type XDCAF/XDCAG/XDCAH/XDCBA Series

RoHS

Lead free

Murata's Crystal Filter with original thin wafer design technology based on long experience and activity realizes high reliability and is widely used in various applications such as business radios.

Features

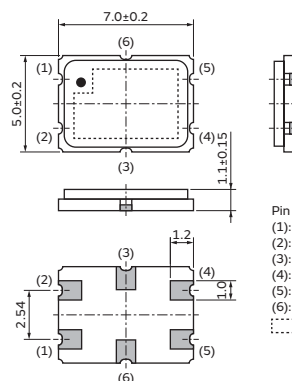
1. Low profile surface mount
2. Customized design and matching service
3. 4-Pole type is a small size in one package

Applications

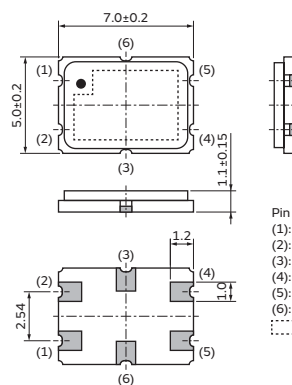
1. Radio communication
2. Base Station
3. Communication (IF) other



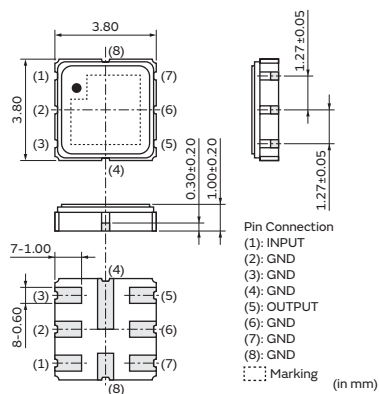
XDCAF



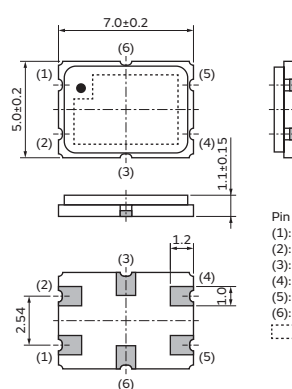
XDCAG



XDCBA



XDCAH



Series

| Series | Size | Center Frequency (MHz) | Number of Poles |
|--------|------|------------------------|-----------------|
| XDCAF | 7050 | 20 to 150 | 2 |
| XDCAG | | | 4 |
| XDCAH | | | 4 |
| XDCBA | 3838 | 45 to 150 | 2 |

Part Number List

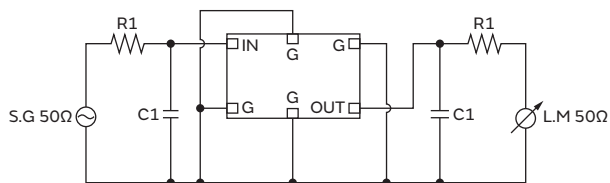
XDCAF/XDCAG/XDCAH 7050 Size (11PN)

| Part Number | Center Frequency (MHz) | Overtone Order | Number of Poles | 3dB Bandwidth (kHz min.) | Stop Band Width (kHz max.) | Guaranteed Attenuation (dB min.) [fo-910kHz] | Spurious (dB min.) within fo±1MHz | Insertion Loss (dB max.) | Ripple (dB max.) | Operating Temperature Range (°C) |
|--------------------|------------------------|----------------|-----------------|--------------------------|----------------------------|--|-----------------------------------|--------------------------|------------------|----------------------------------|
| XDCAF21M400RAA00P0 | 21.4000 | Fundamental | 2 | ±7.5 | ±25 @18dB | 70 | 10 | 2.0 | 1.0 | -20 to +70 |
| XDCAF21M700MAA00P0 | 21.7000 | Fundamental | 2 | ±3.75 | ±20 @18dB | 70 | 18 | 2.0 | 1.0 | -20 to +70 |
| XDCAG38M850PGA00P0 | 38.8500 | Fundamental | 4 | ±5.0 | ±25 @45dB | 70 | 40 | 5.0 | 1.0 | -20 to +70 |
| XDCAG44M850QGA00P0 | 44.8500 | Fundamental | 4 | ±6.5 | ±12.5 @20dB | 70 | 40 | 3.0 | 1.0 | -20 to +70 |
| XDCAG45M000RGA00P0 | 45.0000 | Fundamental | 4 | ±7.5 | ±25 @25dB | 70 | 40 | 3.0 | 1.0 | -20 to +70 |
| XDCAG46M350PGA00P0 | 46.3500 | Fundamental | 4 | ±5.0 | ±20 @35dB | 70 | 40 | 5.0 | 1.0 | -20 to +70 |
| XDCAG49M950PGA00P0 | 49.9500 | Fundamental | 4 | ±5.0 | ±20 @40dB | 70 | 40 | 5.0 | 1.0 | -20 to +70 |
| XDCAG51M650PGA00P0 | 51.6500 | Fundamental | 4 | ±5.0 | ±12.5 @20dB | 70 | 40 | 5.0 | 1.0 | -20 to +70 |
| XDCAG58M050MGA00P0 | 58.0500 | Fundamental | 4 | ±4.0 | ±20 @38dB | 70 | 40 | 5.0 | 1.0 | -20 to +70 |
| XDCAH50M850PHA00P0 | 50.8500 | Fundamental | 4 | ±5.0 | ±25 @45dB | 80 | 60 | 5.0 | 1.0 | -20 to +70 |
| XDCAH73M350QHA03P0 | 73.3500 | Fundamental | 4 | ±6.0 | ±25 @40dB | 80 | 60 | 4.0 | 1.0 | -20 to +70 |

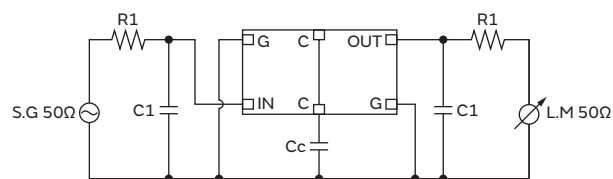
XDCBA 3838 Size (3PN)

| Part Number | Center Frequency (MHz) | Overtone Order | Number of Poles | 3dB Bandwidth (kHz min.) | Stop Band Width (kHz max.) | Guaranteed Attenuation (dB min.) [fo-910kHz] | Spurious (dB min.) within fo±1MHz | Insertion Loss (dB max.) | Ripple (dB max.) | Operating Temperature Range (°C) |
|--------------------|------------------------|----------------|-----------------|--------------------------|----------------------------|--|-----------------------------------|--------------------------|------------------|----------------------------------|
| XDCBA47M250RAA02P0 | 47.2500 | Fundamental | 2 | ±7.5 | ±25 @15dB | 60 | 10 [fo+30kHz to 1000kHz] | 2.0 | 1.0 | -20 to +70 |
| XDCBA50M000MAA01P0 | 50.0000 | Fundamental | 2 | ±3.75 | ±16 @15dB | 50 | 20 [fo+100kHz to 1000kHz] | 3.0 | 1.0 | -20 to +70 |
| XDCBA70M200TAA01P0 | 70.2000 | Fundamental | 2 | ±12.5 | ±60 @18dB | 50 | 5 [fo+100kHz to 1000kHz] | 2.5 | 1.0 | -20 to +70 |

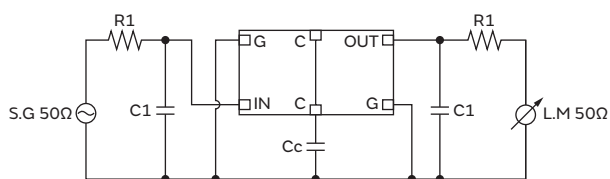
Test circuit



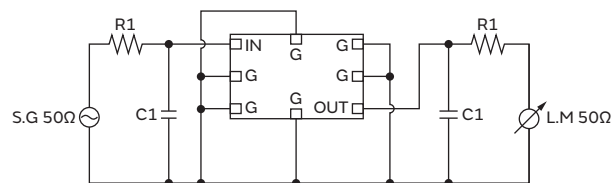
| Part Number | R1 (Ω) | C1 (pF) |
|---------------------------|--------|---------|
| XDCAF21M400RAA00P0 | 1450 | 2.5 |
| XDCAF21M700MAA00P0 | 800 | 8.0 |



| Part Number | R1 (Ω) | C1 (pF) | Cc (pF) |
|---------------------------|--------|---------|---------|
| XDCAG38M850PGA00P0 | 560 | 3.0 | 14.0 |
| XDCAG58M050MGA00P0 | 200 | 7.3 | 21.7 |



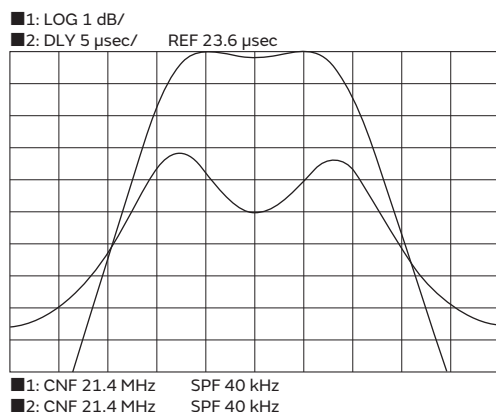
| Part Number | R1 (Ω) | C1 (pF) | Cc (pF) |
|---------------------------|--------|---------|---------|
| XDCAH50M850PHA00P0 | 510 | 4.0 | 11.0 |
| XDCAH73M350QHA03P0 | 400 | 4.0 | 9.2 |



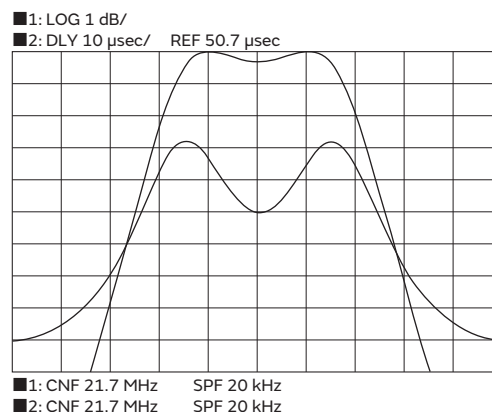
| Part Number | R1 (Ω) | C1 (pF) |
|---------------------------|--------|---------|
| XDCBA47M250RAA02P0 | 420 | 6.0 |
| XDCBA50M000MAA01P0 | 220 | 7.5 |
| XDCBA70M200TAA01P0 | 680 | -1.0 |

Frequency Characteristics

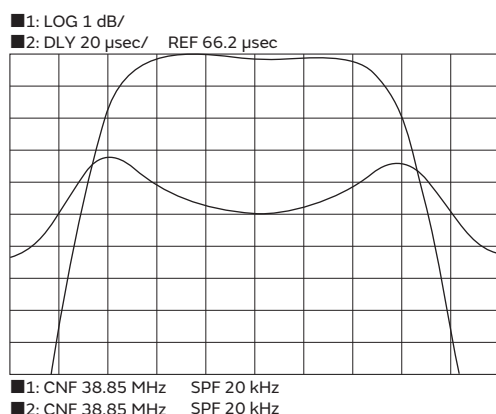
XDCAF21M400RAA00P0



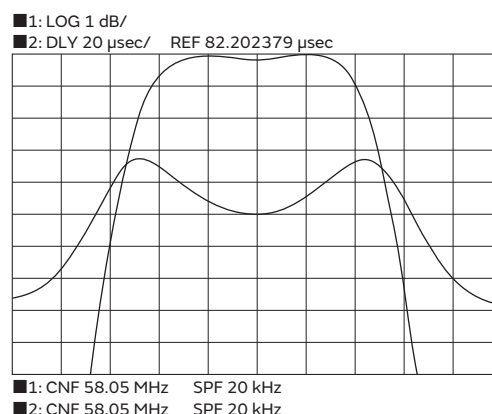
XDCAF21M700MAA00P0



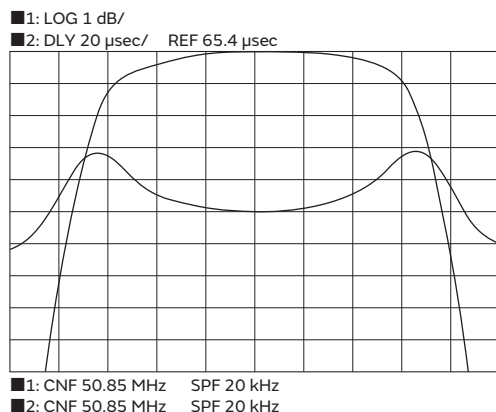
XDCAG38M850PGA00P0



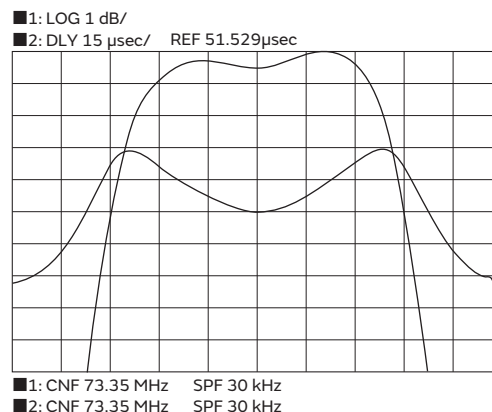
XDCAG58M050MGA00P0



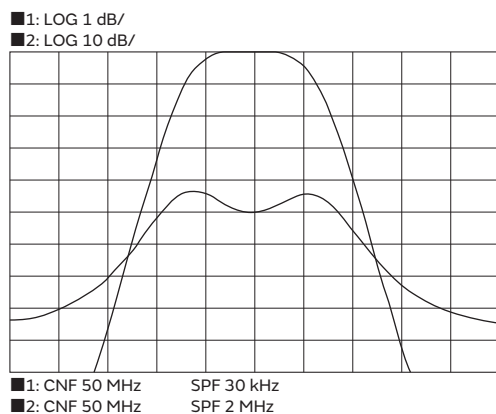
XDCAH50M850PHA00P0



XDCAH73M350QHA03P0

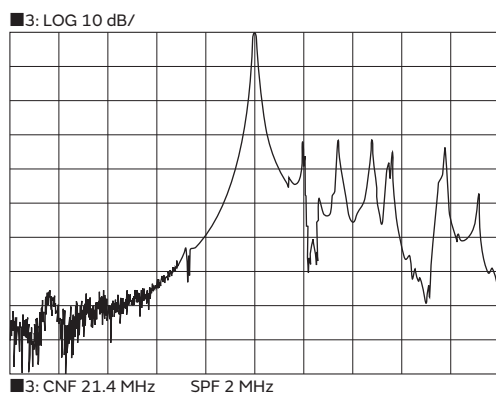


XDCBA50M000MAA01P0

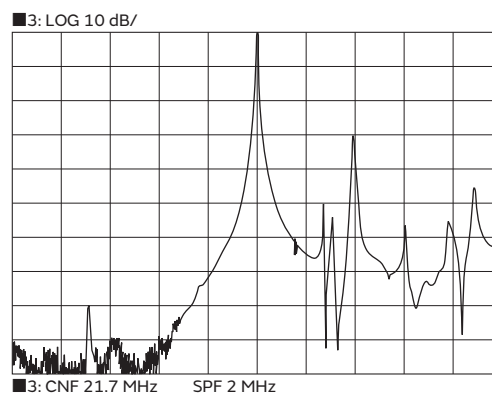


Spurious

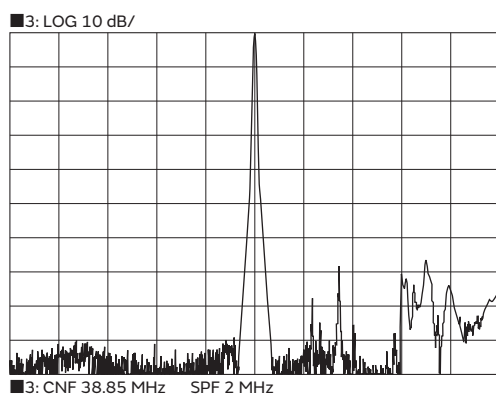
XDCAF21M400RAA00P0



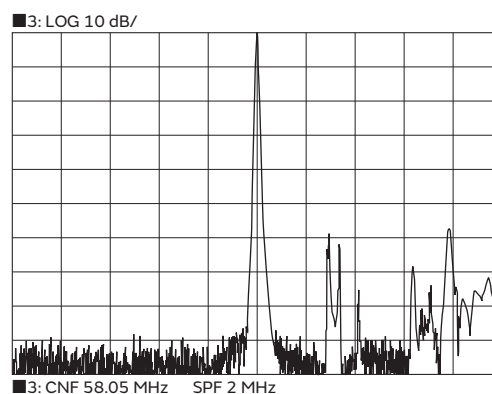
XDCAF21M700MAA00P0



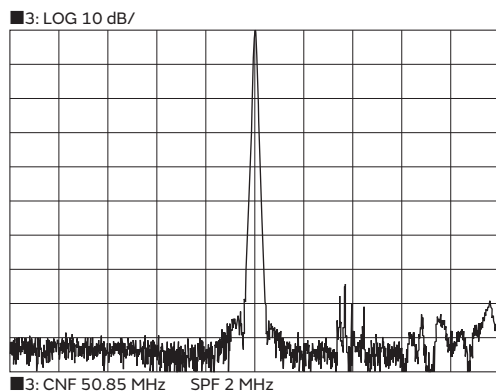
XDCAG38M850PGA00P0



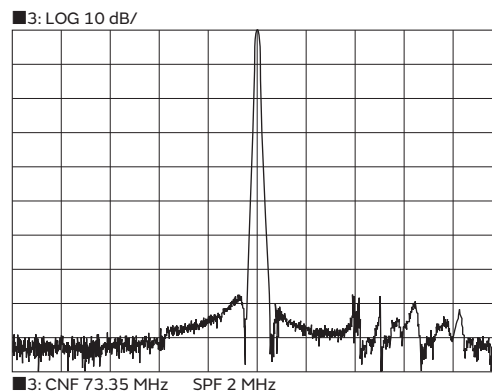
XDCAG58M050MGA00P0



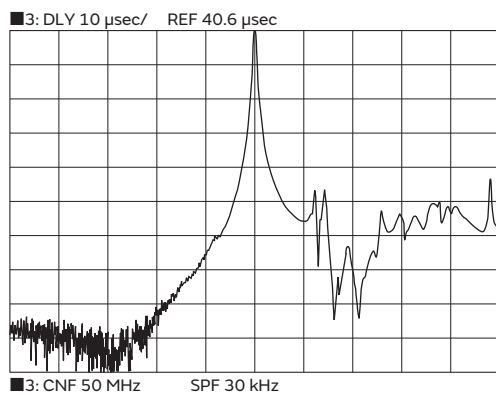
XDCAH50M850PHA00P0



XDCAH73M350QHA03P0



XDCBA50M000MAA01P0



Notice

Crystal Filters Chip Type XDCAF/XDCAG/XDCAH/XDCBA Series

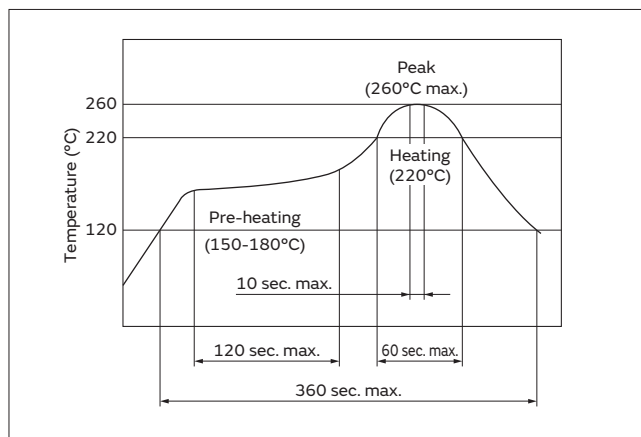
— Soldering and Mounting —

1. Standard Reflow Soldering Conditions

(1) Reflow

Filter is soldered twice within the following temperature conditions.

Flux: Please use rosin based flux, but do not use water soluble flux.



(2) Soldering Iron

If compelled to mount the component by using a soldering iron, please do not directly touch the component with the soldering iron. The component terminals or electrical characteristics may be damaged if excessive thermal stress is applied.

| | Condition |
|-------------------------------|-------------|
| Heating of the Soldering Iron | 350°C max. |
| Soldering Time | 5 sec. max. |

2. Wash

Do not clean or wash the component.

— Storage and Operating Conditions —

1. Product Storage Condition

Please store the products in a room where the temperature/humidity is stable, and avoid places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to + 40°C

Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the solderability may be degraded due to storage under poor conditions.

Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

(1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because the characteristics may be reduced in quality and may be degraded in solderability due to storage in a chemical atmosphere.

- (2) Please do not put the products directly on the floor without anything under them to avoid damp places and/or dusty places.
- (3) Please do not store the products in places such as a damp heated place or any place exposed to direct sunlight or excessive vibration.
- (4) Please use the products immediately after the package is opened, because the characteristics may be reduced in quality and/or be degraded in solderability due to storage under poor conditions.
- (5) Please do not drop the products to avoid cracking of the ceramic element.

4. Other

- (1) Please be sure to consult with our sales representative or engineer whenever the products are to be used in conditions not listed above.

Continued on the following page. ↗

Notice

Continued from the preceding page. ↘

— Rating —

The component may be damaged if excessive mechanical stress is applied.

— Handling —

- (1) For safety purposes, connect the output of filters to the IF amplifier through a D.C. blocking capacitor. Avoid applying a direct current to the output of filters.
- (2) The component is recommended for placement machines employing optical placement capabilities. The component might be damaged by mechanical force depending on placement machine and condition. Make sure that you have evaluated by using placement machines before going into mass production. Do not use placement machines employing mechanical positioning. Please contact Murata for details beforehand.
- (3) Do not reuse components once mounted onto a circuit board.
- (4) Crystal Filter
You are requested to approve our data sheet and confirm the environment surrounding a crystal filter as well.
In order to demonstrate sufficient performance, please read the following notes.
 - (4)-1 Necessity for LC Tuned Circuit
When the stray capacitance of the PCB that mounts a crystal filter is large, a tuned circuit for offsetting the stray capacitance may be needed.
 - (4)-2 Termination Impedance
The original characteristic in a pass band, insertion loss, ripple and bandwidth characteristic are no longer acquired when termination impedance differs from a rated value. The circuit impedance shall be measured accurately and it has consistency to match on termination conditions.
Please keep in mind that a passage region will move in particular, if termination impedance does not match.

(4)-3 Maximum Level

An input level shall be less than a rated value.

If the input level beyond a rated value impressed, a crystal resonance characteristic will be deteriorated and the original characteristic will no longer be acquired as a crystal filter.

(4)-4 Separation between Input and Output

In order to prevent electromagnetic combination between input and output, please have shielded certainly. If it has the combination between input and output, the incoming signal may go to the output side directly in the attenuation domain. The amount of guarantee attenuation will less achievable and the original characteristic of crystal filter will no longer be acquired.

There is grounding as one of the method. It enables to have the crystal filter grounded with attachment screw or grounding terminal.

The internal part of crystal filter may be damaged, if it solders to a case directly. In addition the case of a crystal filter is grounded certainly because potential difference can be eliminated at the circuit side.

(4)-5 Direct-Current Superposition

When you charge direct-current, please do not have the current beyond a rated current value. Internal transformer will generate a heat and it will create a cause of bad insulation or disconnection, if excess direct current goes through filter than the rated value.

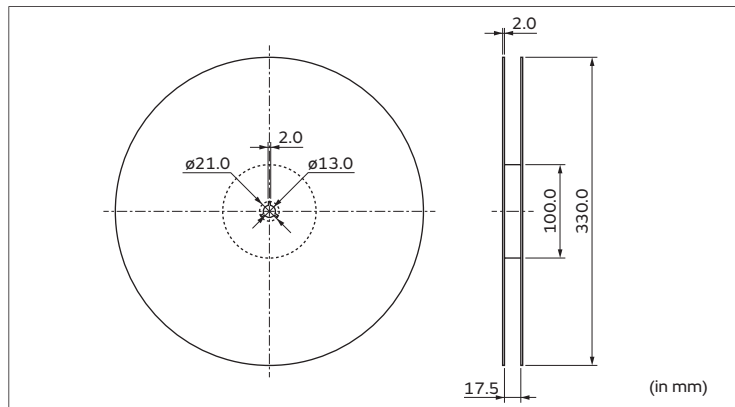
Packaging

Minimum Quantity/Dimensions of Reel (XDCAF/XDCAG/XDCAH Series)

Embossed Tape ø330mm

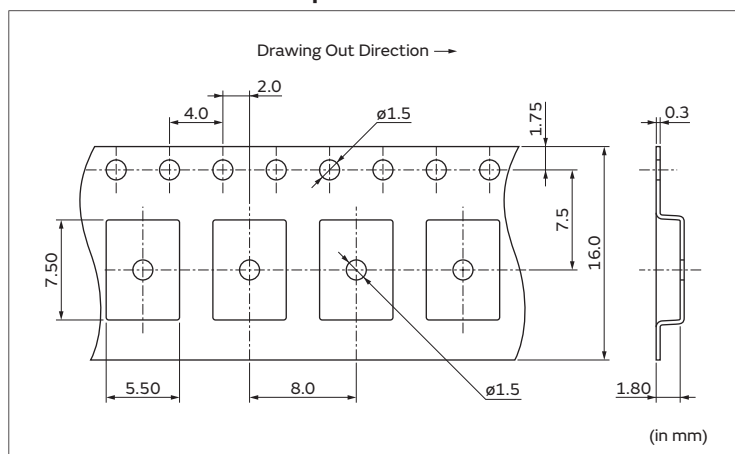
3,000

(pcs.)



4

Dimensions of Carrier Tape



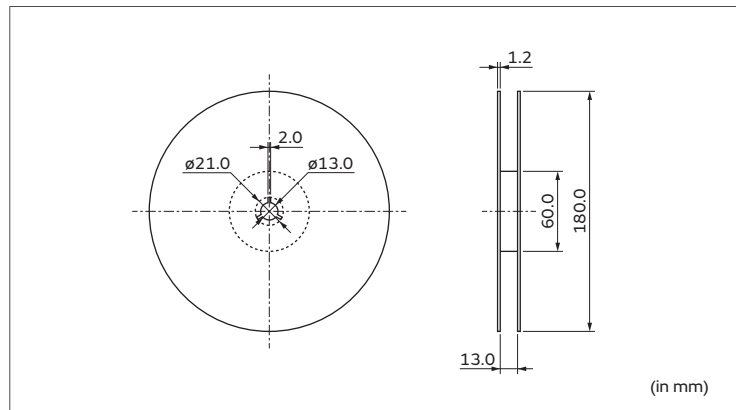
Packaging

Minimum Quantity/Dimensions of Reel (XDCBA Series)

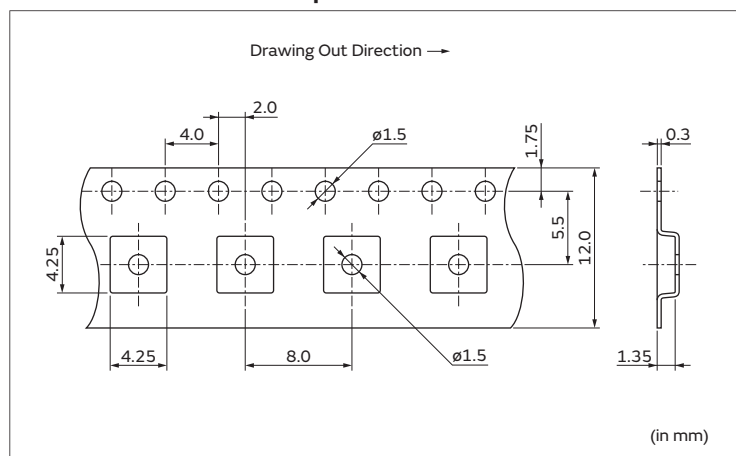
Embossed Tape $\phi 180\text{mm}$

1,000

(pcs.)



Dimensions of Carrier Tape



Global Locations

For details please visit www.murata.com



⚠ Note

1 Export Control

For customers outside Japan:

No Murata products should be used or sold, through any channels, for use in the design, development, production, utilization, maintenance or operation of, or otherwise contribution to (1) any weapons (Weapons of Mass Destruction [nuclear, chemical or biological weapons or missiles] or conventional weapons) or (2) goods or systems specially designed or intended for military end-use or utilization by military end-users.

For customers in Japan:

For products which are controlled items subject to the "Foreign Exchange and Foreign Trade Law" of Japan, the export license specified by the law is required for export.

2 Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.

- ① Aircraft equipment
- ② Aerospace equipment
- ③ Undersea equipment
- ④ Power plant equipment
- ⑤ Medical equipment
- ⑥ Transportation equipment (vehicles, trains, ships, etc.)
- ⑦ Traffic signal equipment
- ⑧ Disaster prevention / crime prevention equipment
- ⑨ Data-processing equipment
- ⑩ Application of similar complexity and/or reliability requirements to the applications listed above

3 Product specifications in this catalog are as of October 2019. They are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering. If there are any questions, please contact our sales representatives or product engineers.

4 Please read rating and ⚠CAUTION (for storage, operating, rating, soldering, mounting and handling) in this catalog to prevent smoking and/or burning, etc.

5 This catalog has only typical specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

6 Please note that unless otherwise specified, we shall assume no responsibility whatsoever for any conflict or dispute that may occur in connection with the effect of our and/or a third party's intellectual property rights and other related rights in consideration of your use of our products and/or information described or contained in our catalogs. In this connection, no representation shall be made to the effect that any third parties are authorized to use the rights mentioned above under licenses without our consent.

7 No ozone depleting substances (ODS) under the Montreal Protocol are used in our manufacturing process.

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